

CDX-656/656X

SERVICE MANUAL

Ver 1.0 2001.11

US Model
Canadian Model
AEP Model
UK Model
CDX-656
E Model
CDX-656X



Photo: CDX-656X

Model Name Using Similar Mechanism	CDX-646/646X
CD Drive Mechanism Type	MG-251B-137
Optical Pick-up Name	KSS-720A

SPECIFICATIONS

System	Compact disc digital audio system
Laser diode properties	Material: GaAlAs Wavelength: 780 nm Emission Duration: Continuous Laser out-put Power: Less than 44.6 μ W*
Frequency response	10 – 20,000 Hz
Wow and flutter	Below the measurable limit
Signal-to-noise ratio	94 dB
Outputs	BUS control output (8 pins) Analog audio output (RCA pin)
Current drain	800 mA (during CD playback) 800 mA (during loading or ejecting a disc)
Operating temperature	–10°C to +55°C (14°F to 131°F)
Dimensions	Approx. 262 × 90 × 185 mm (10 ³ /8 × 3 ⁵ /8 × 7 ³ /8 in.) (w/h/d) not incl. projecting parts and controls
Mass	Approx. 2.1 kg (4 lb. 10 oz.)
Power requirement	12 V DC car battery (negative ground)
Supplied accessories	Disc magazine (1) Parts for installation and connections (1 set)

Design and specifications are subject to change without notice.

COMPACT DISC CHANGER

9-873-375-01
2001K0500-1
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e Vehicle Company
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SERVICING NOTES

NOTES ON HANDLING THE OPTICAL PICK-UP BLOCK OR BASE UNIT

The laser diode in the optical pick-up block may suffer electrostatic breakdown because of the potential difference generated by the charged electrostatic load, etc. on clothing and the human body. During repair, pay attention to electrostatic breakdown and also use the procedure in the printed matter which is included in the repair parts.

The flexible board is easily damaged and should be handled with care.

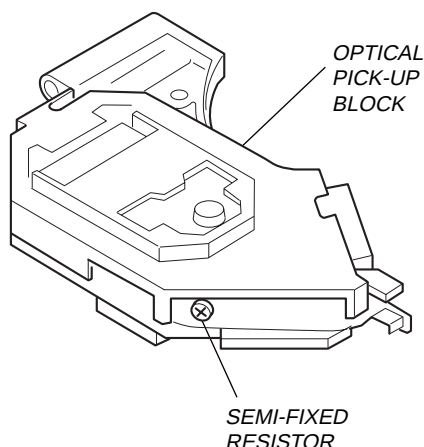
NOTES ON LASER DIODE EMISSION CHECK

The laser beam on this model is concentrated so as to be focused on the disc reflective surface by the objective lens in the optical pick-up block. Therefore, when checking the laser diode emission, observe from more than 30 cm away from the objective lens.

US/Canadian model:

If the optical pick-up block is defective, please replace the whole optical pick-up block.

Never turn the semi-fixed resistor located at the side of optical pick-up block.



AEP/UK model:

CLASS 1
LASER PRODUCT

This product is classified as a CLASS 1 LASER PRODUCT.

The CLASS 1 LASER PRODUCT label is located on the rear exterior.

CAUTION—INVISIBLE LASER RADIATION WHEN OPEN
DO NOT STARE INTO BEAM OR
VIEW DIRECTLY WITH OPTICAL INSTRUMENTS

This label is located on the drive unit's internal chassis.

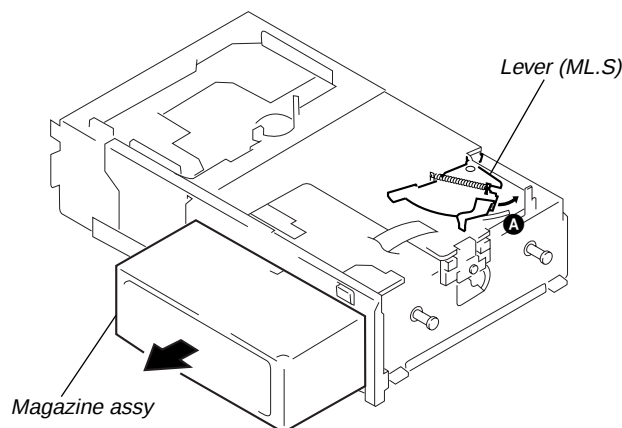
When replacing the chassis (U.S) sub assy of mechanism deck which have the "CAUTION LABEL" attached, please be sure to put a new CAUTION LABEL (3-223-913-11) to the chassis (U.S) sub assy.

DISC MAGAZINE GETTING OUT PROCEDURE ON THE POWER SUPPLY IS OFF

Remove the CASE (LOWER. T) beforehand

- 1) Press the lever (ML.S) assy in the direction of arrow **A**.
- 2) Removal the magazine assy.

Note: Take out the magazine only when the tray is completely within the magazine. If the disk or tray is sticking out, turn on the power and eject the magazine.



CAUTION

Use of controls or adjustments or performance of procedures other than those specified herein may result in hazardous radiation exposure.

Flexible Circuit Board Repairing

- Keep the temperature of the soldering iron around 270 °C during repairing.
- Do not touch the soldering iron on the same conductor of the circuit board (within 3 times).
- Be careful not to apply force on the conductor when soldering or unsoldering.

Notes on chip component replacement

- Never reuse a disconnected chip component.
- Notice that the minus side of a tantalum capacitor may be damaged by heat.

SAFETY-RELATED COMPONENT WARNING!!

COMPONENTS IDENTIFIED BY MARK $\triangle$ OR DOTTED LINE WITH MARK $\triangle$ ON THE SCHEMATIC DIAGRAMS AND IN THE PARTS LIST ARE CRITICAL TO SAFE OPERATION. REPLACE THESE COMPONENTS WITH SONY PARTS WHOSE PART NUMBERS APPEAR AS SHOWN IN THIS MANUAL OR IN SUPPLEMENTS PUBLISHED BY SONY.

ATTENTION AU COMPOSANT AYANT RAPPORT À LA SÉCURITÉ!

LES COMPOSANTS IDENTIFIÉS PAR UNE MARQUE $\triangle$ SUR LES DIAGRAMMES SCHÉMATIQUES ET LA LISTE DES PIÈCES SONT CRITIQUES POUR LA SÉCURITÉ DE FONCTIONNEMENT. NE REMPLACER CES COMPOSANTS QUE PAR DES PIÈCES SONY DONT LES NUMÉROS SONT DONNÉS DANS CE MANUEL OU DANS LES SUPPLÉMENTS PUBLIÉS PAR SONY.

TEST DISC

This set can playback a CD-R, CD-RW for audio use. When test this set, use the following test disc.

Test disc for CD-R: TCD-R082LMT (Part No.: J-2501-063-1)

Test disc for CD-RW: TCD-W082L (Part No.: J-2501-063-2)

Notes on CD-R/CD-RW discs

- You can play CD-Rs/CD-RWs (recordable CDs/rewritable CDs) designed for audio use on this unit (fig. [H]).
 - Some CD-Rs/CD-RWs (depending on the equipment used for its recording or the condition of the disc) may not play on this unit.
 - You cannot play a CD-R/CD-RW that is not finalized*.
- * A process necessary for a recorded CD-R/CD-RW disc to be played on the audio CD player.

[H] Look for this mark to distinguish CD-Rs/CD-RWs for audio use.



This mark denotes that a disc is not for audio use.



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Inserción de discos

- Puede reproducir discos CD-R/CD-RW (discos compactos grabables/discos compactos reescribibles) diseñados para uso de audio en esta unidad (fig. [H]).
- Determinados discos CD-R/CD-RW (dependiendo del equipo utilizado para su grabación o la condición del disco) pueden no reproducirse en esta unidad.
- No es posible reproducir discos CD-R/CD-RW no finalizados*.

* Proceso necesario para reproducir en el reproductor de CD de audio los discos CD-R/CD-RW grabados.

4

Installation

Precautions

- Choose the mounting location carefully, observing the following:
 - The unit is not subject to temperatures exceeding 55°C (131°F) (such as in a car parked in direct sunlight).
 - The unit is not subject to direct sunlight.
 - The unit is not near heat sources (such as heaters).
 - The unit is not exposed to rain or moisture.
 - The unit is not exposed to excessive vibration.
 - The fuel tank should not be damaged by the tapping screws.
 - There should be no wire harnesses or pipes under the place where you are going to install the unit.
 - The spare tire, tools or other equipment in or under the trunk should not be interfered with or damaged by the screws or the unit itself.
- Be sure to use only the supplied mounting hardware for a safe and secure installation.
- Use only the supplied screws.
- Make holes of ø 3.5 mm (7/32 in.) only after making sure there is nothing on the other side of the mounting surface.

How to install the unit

The brackets ① provide two positions for mounting, high and low. Use the appropriate screw holes according to your preference.

Horizontal installation

1

2

Vertical installation

1

2

Suspended installation

When the unit is to be installed under the rear tray etc. in the trunk compartment, make sure the following provisions are made.

- Choose the mounting location carefully so that the unit can be installed horizontally.
- Make sure the unit does not hinder the movement of the torsion bar spring etc. of the trunk lid.

Installation suspendue

Si l'appareil doit être installé sous la plage arrière dans le coffre, par exemple, observer les précautions suivantes.

- Bien choisir l'emplacement pour pouvoir installer l'appareil à l'horizontale.
- Vérifier que l'appareil ne gêne pas les mouvements du ressort de fermeture du coffre, entre autres.

Instalación suspendida

Si va a instalar la unidad debajo de la bandeja trasera, etc., del maletero, tenga en cuenta lo siguiente:

- Elija el lugar de montaje cuidadosamente de forma que sea posible instalar la unidad horizontalmente.
- Asegúrese de que la unidad no dificulta el movimiento del muelle de la barra de torsión, etc., de la tapa del maletero.

1

2

Inclined installation

After installing the unit, align the dials with one of the marks so that the arrows are as vertical as possible.

Installation inclinée

Après avoir installé l'appareil, alignez les disques sur un repère de façon à ce que les flèches soient dans la position la plus verticale possible.

Instalación inclinada

Una vez instalada la unidad, alinee los diales de forma que una de las marcas de las flechas se encuentre en la posición más vertical posible.

Connections/Connexions/Conexiones

For details, refer to the Installation/Connections manual of the car audio.
Pour plus de détails, consulter le manuel d'installation/connexions de l'autoradio.
Con respecto a los detalles, consulte el manual de instalación/conexiones del sistema de audio del automóvil.

Connection diagram/Schéma de connexion/Diagrama de conexión/

Note
For connecting two or more changers, the XA-C30 source selector (optional) is necessary.

Remarque
Pour raccorder deux ou plusieurs changeurs, le sélecteur de source XA-C30 (en option) est nécessaire.

Nota
Si desea conectar dos o más cambiadores, es preciso utilizar un selector de fuente XA-C30 (opcional).

SECTION 2 DISASSEMBLY

• This set can be disassembled in the order shown below.

2-1. DISASSEMBLY FLOW

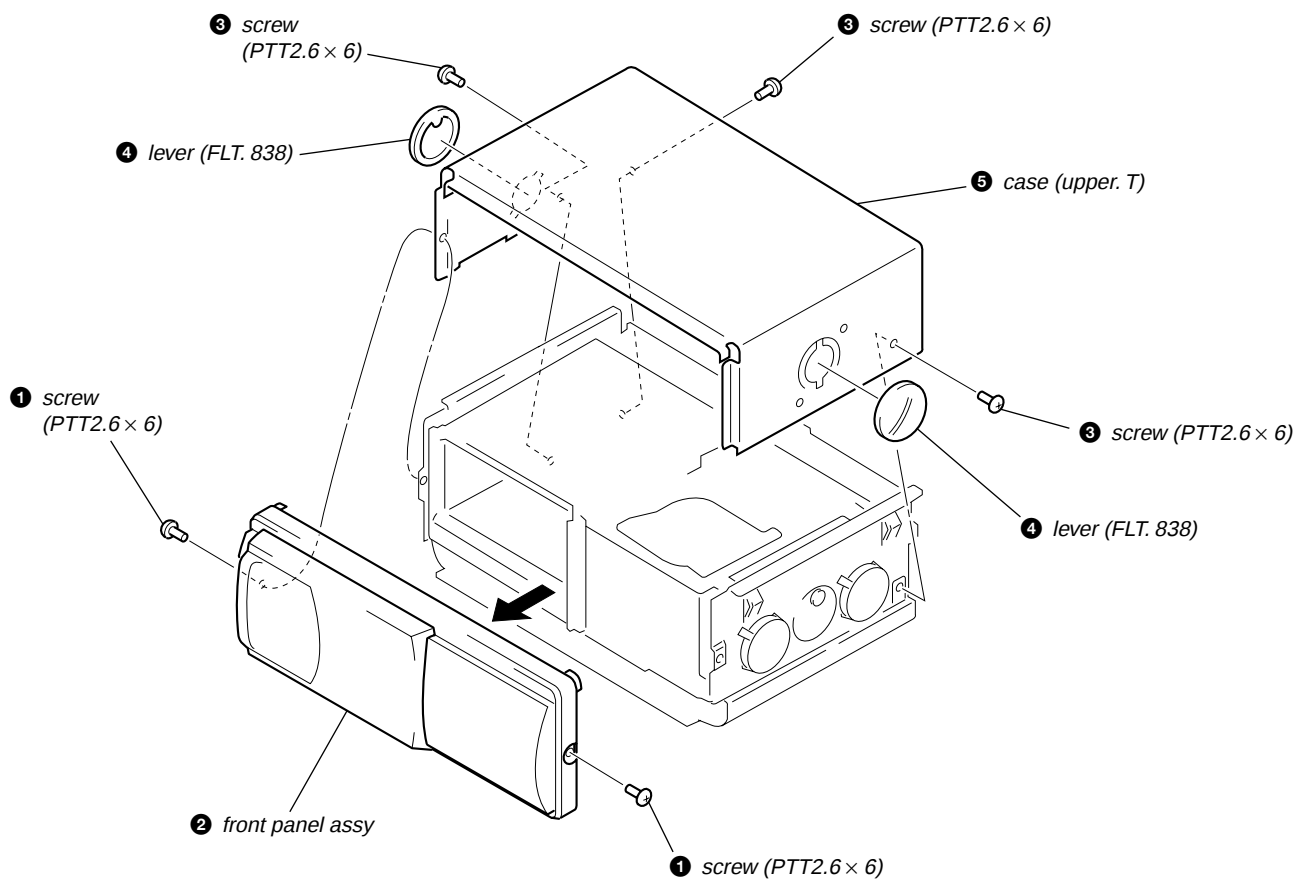
Note 1: The process described in  can be performed in any order.

Note 2: Without completing the process described in , the next process can not be performed.

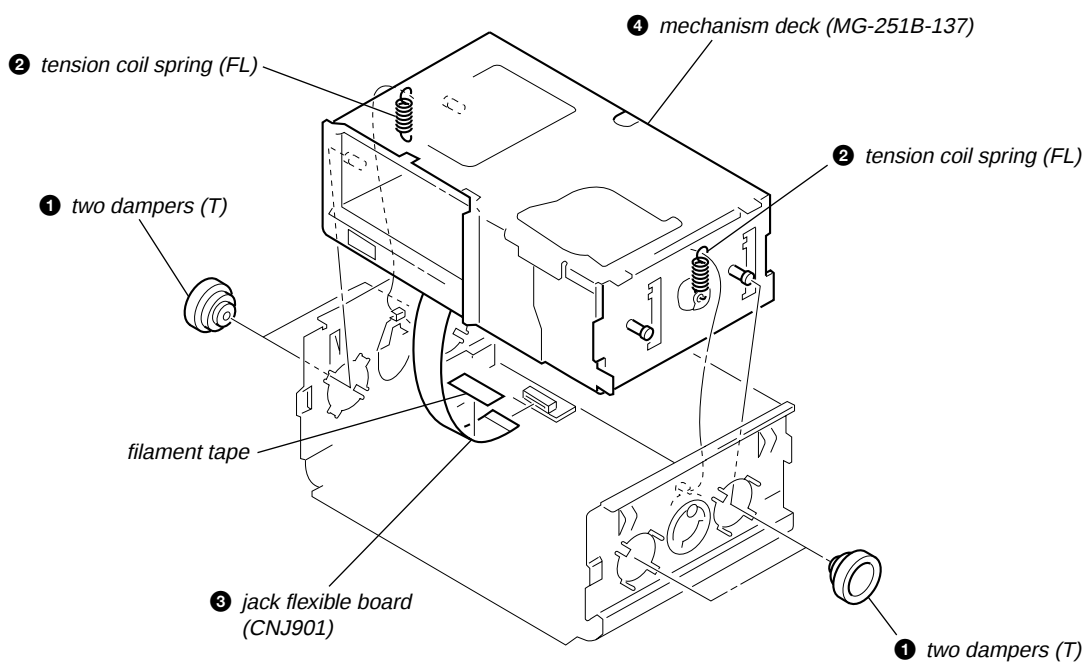


Note: Follow the disassembly procedure in the numerical order given.

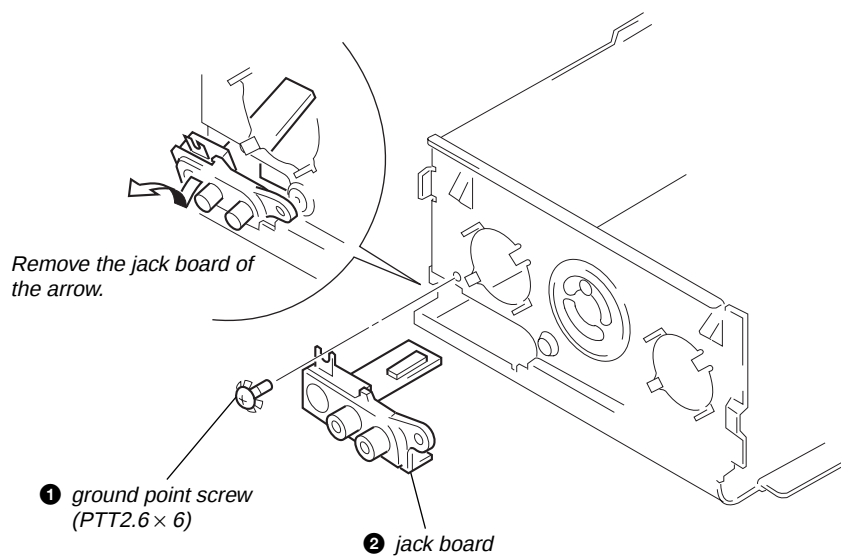
2-2. CASE (UPPER. T), FRONT PANEL ASSY



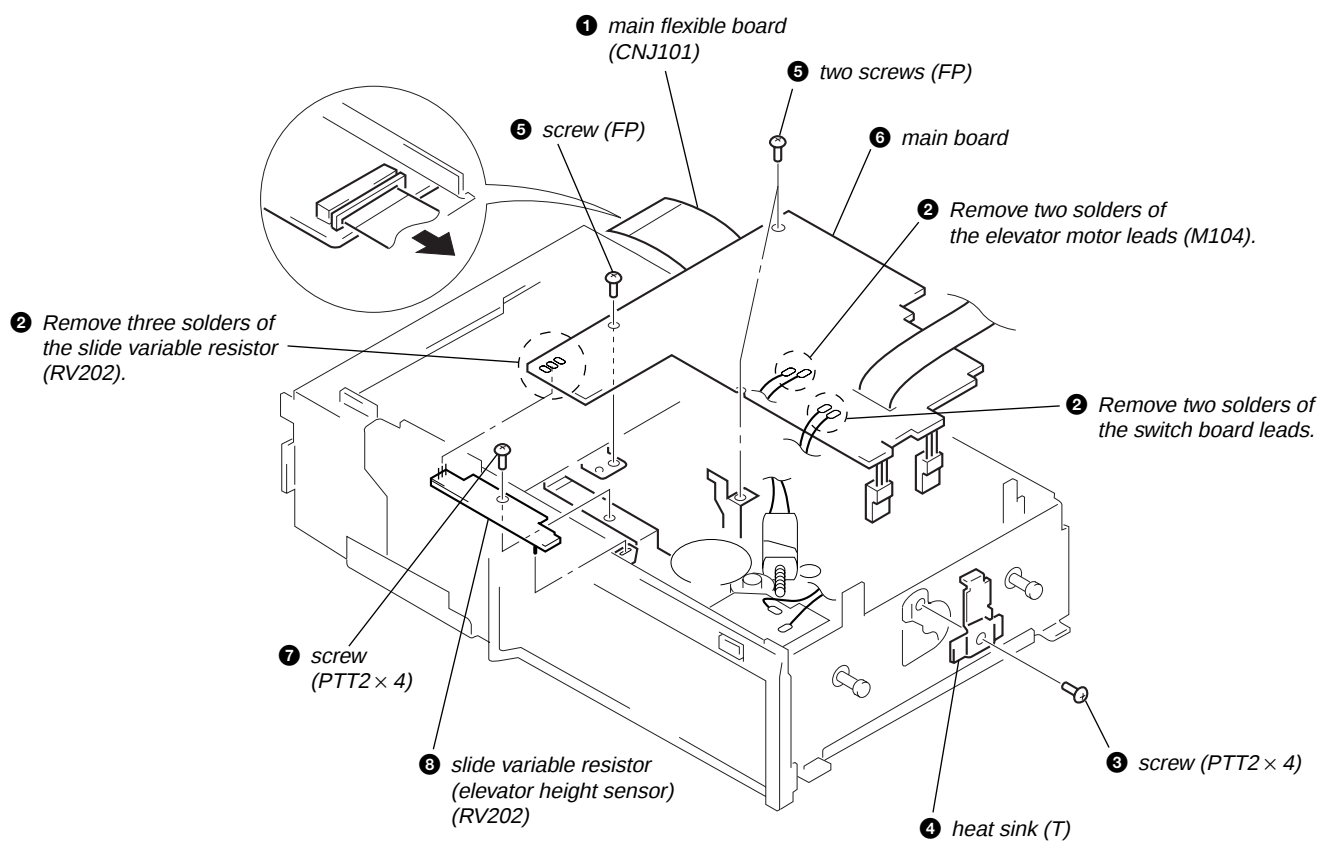
2-3. MECHANISM DECK (MG-251B-137)



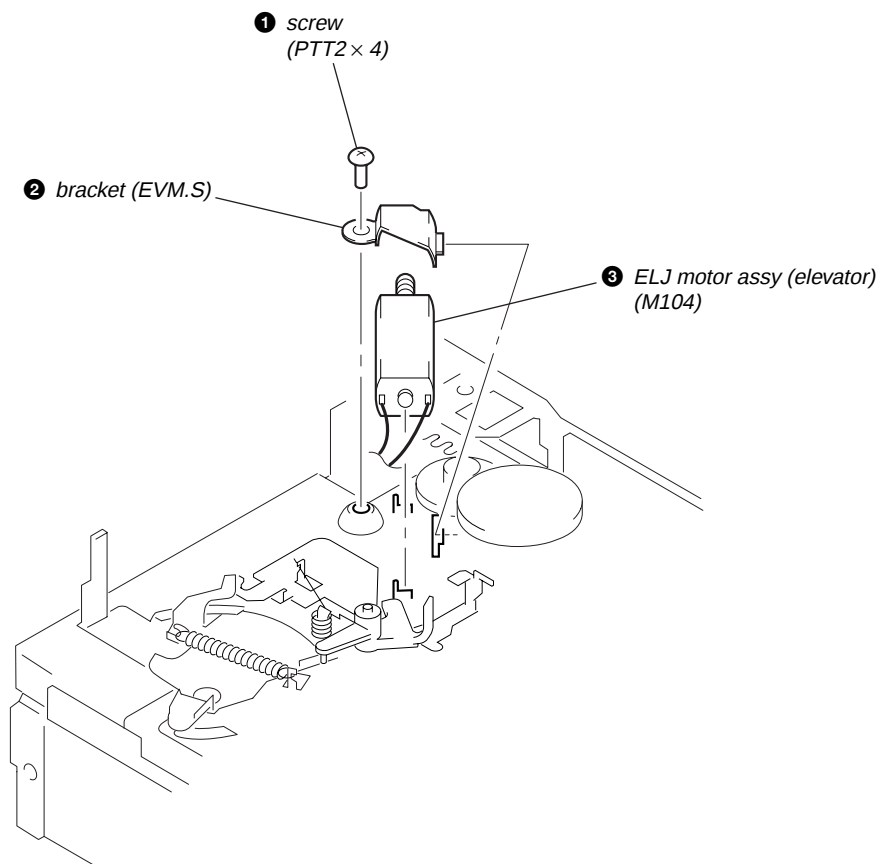
2-4. JACK BOARD



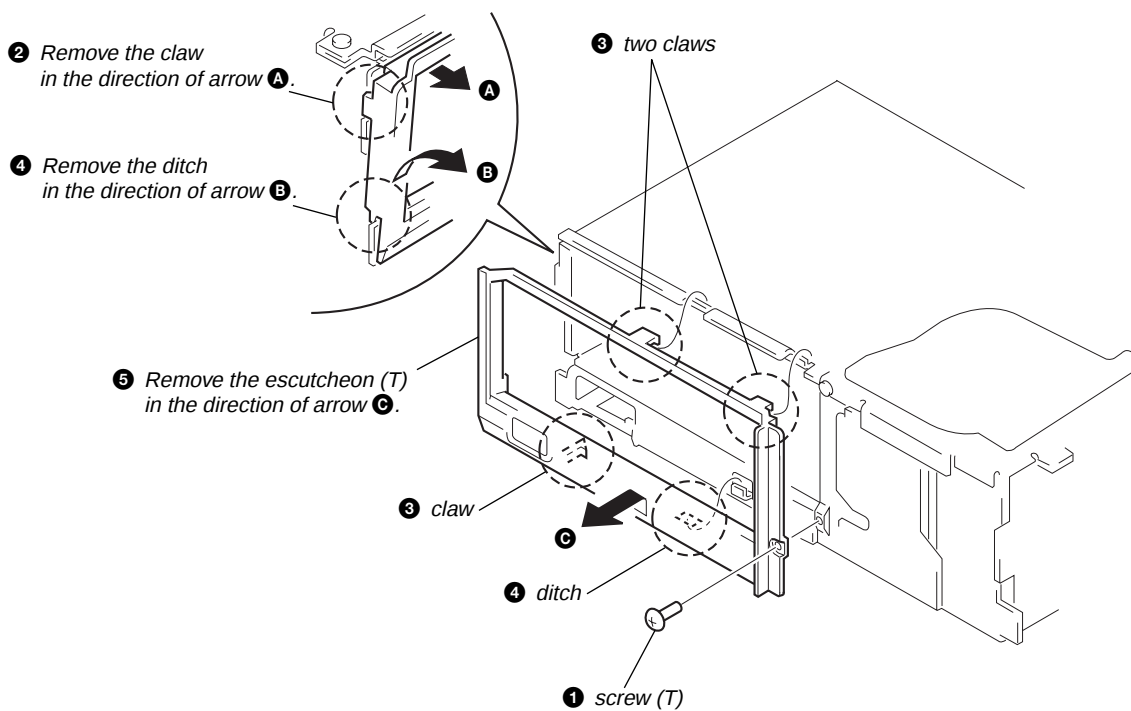
2-5. MAIN BOARD, SLIDE VARIABLE RESISTOR (ELEVATOR HEIGHT SENSOR) (RV202)



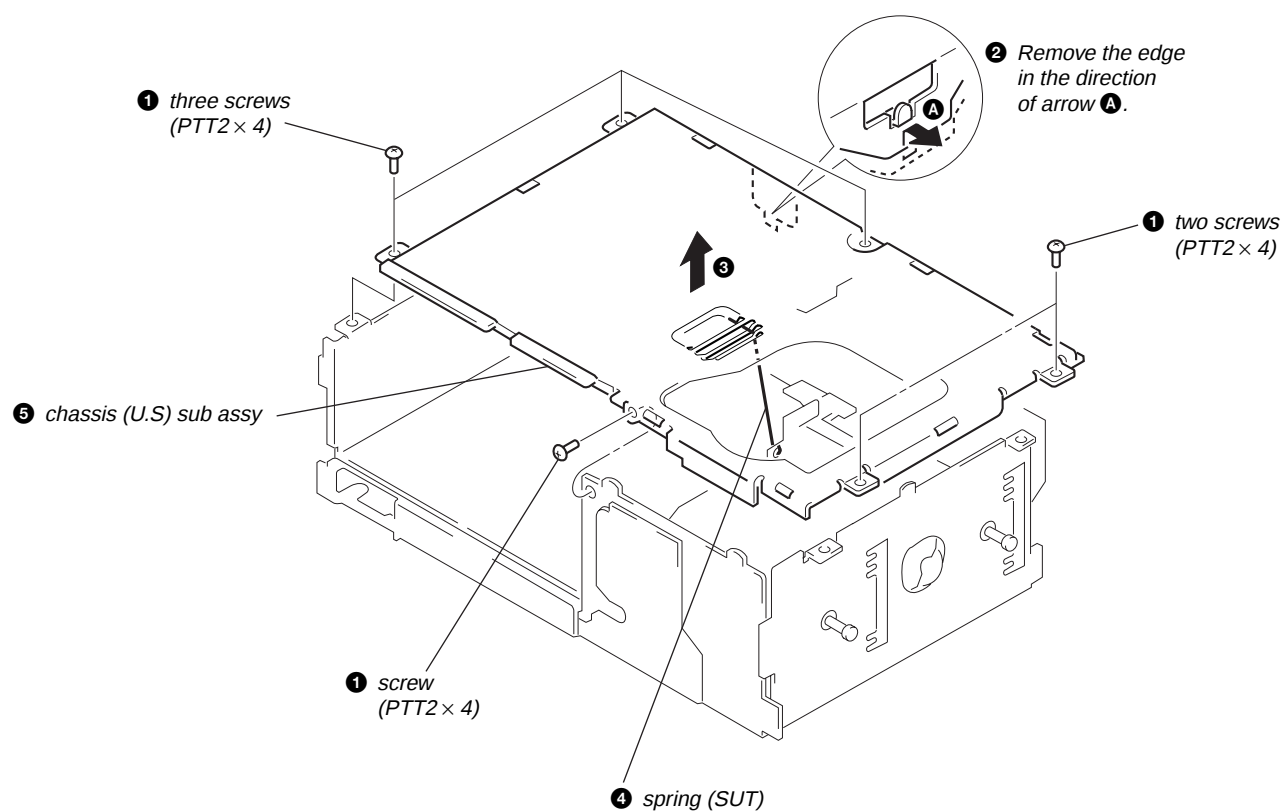
2-6. ELJ MOTOR ASSY (ELEVATOR) (M104)



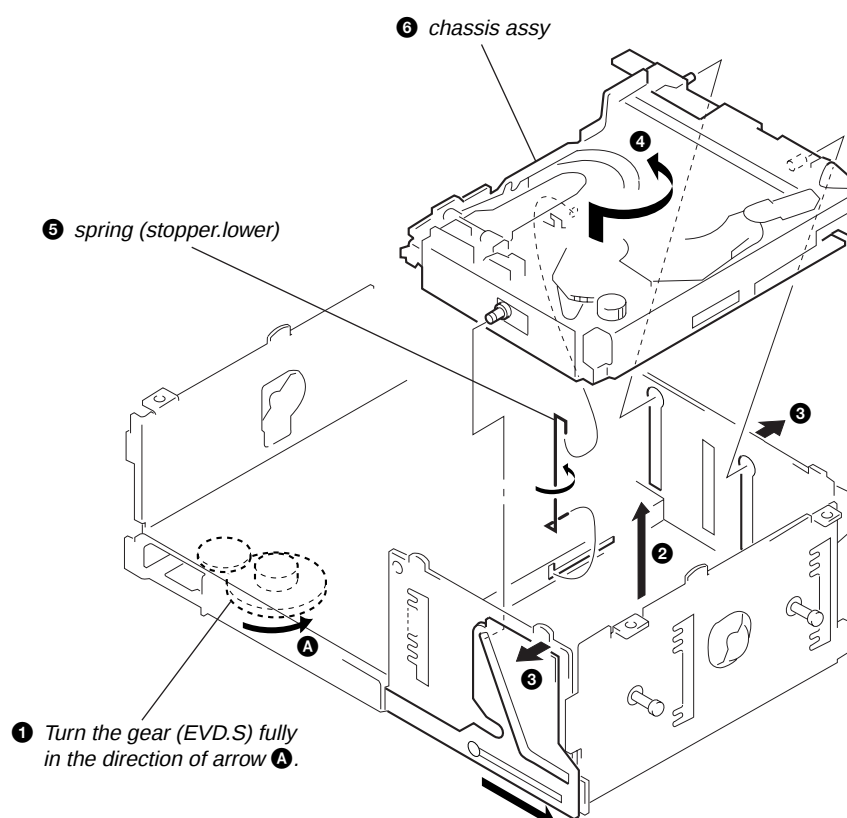
2-7. ESCUTCHEON (T)



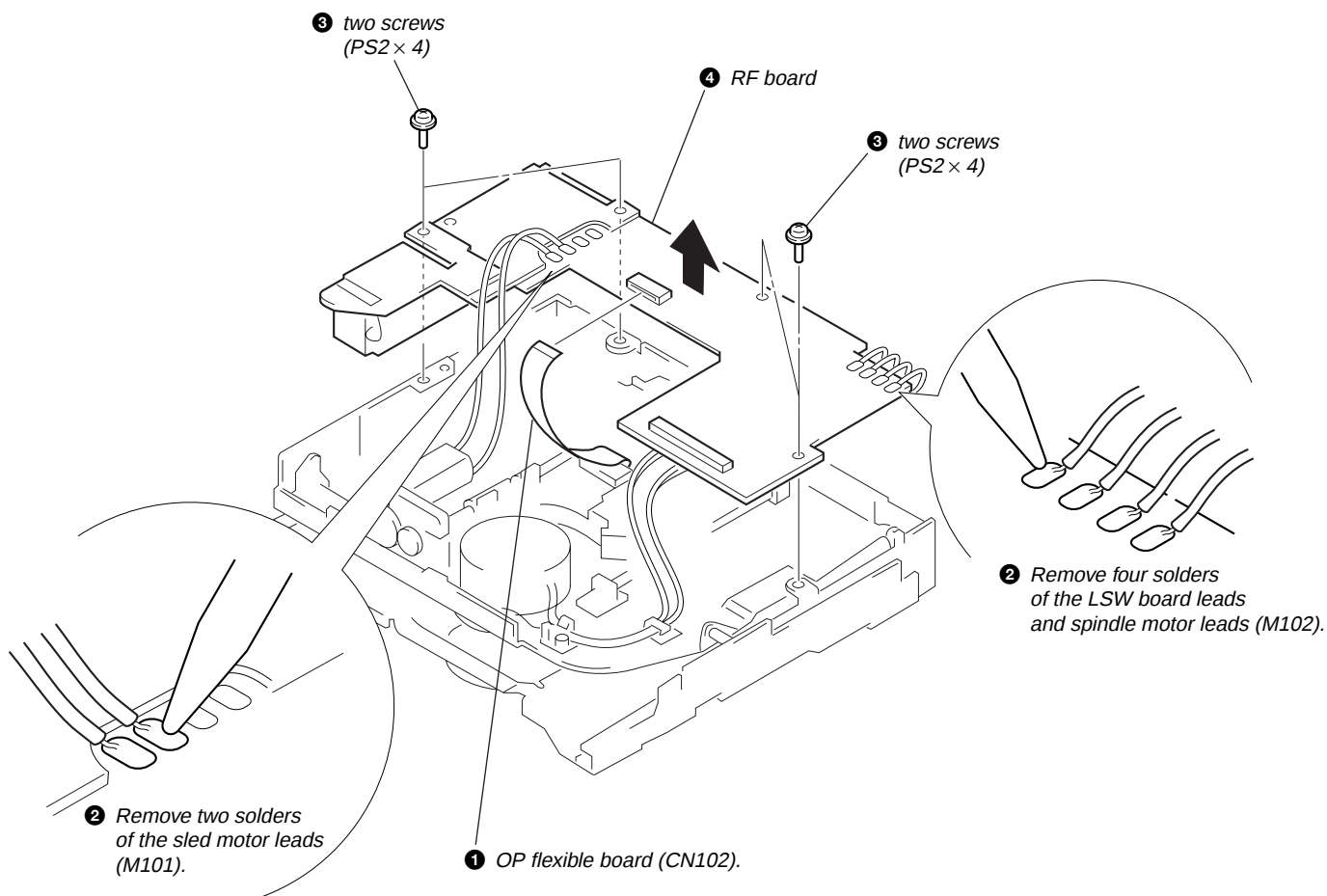
2-8. CHASSIS (U.S) SUB ASSY



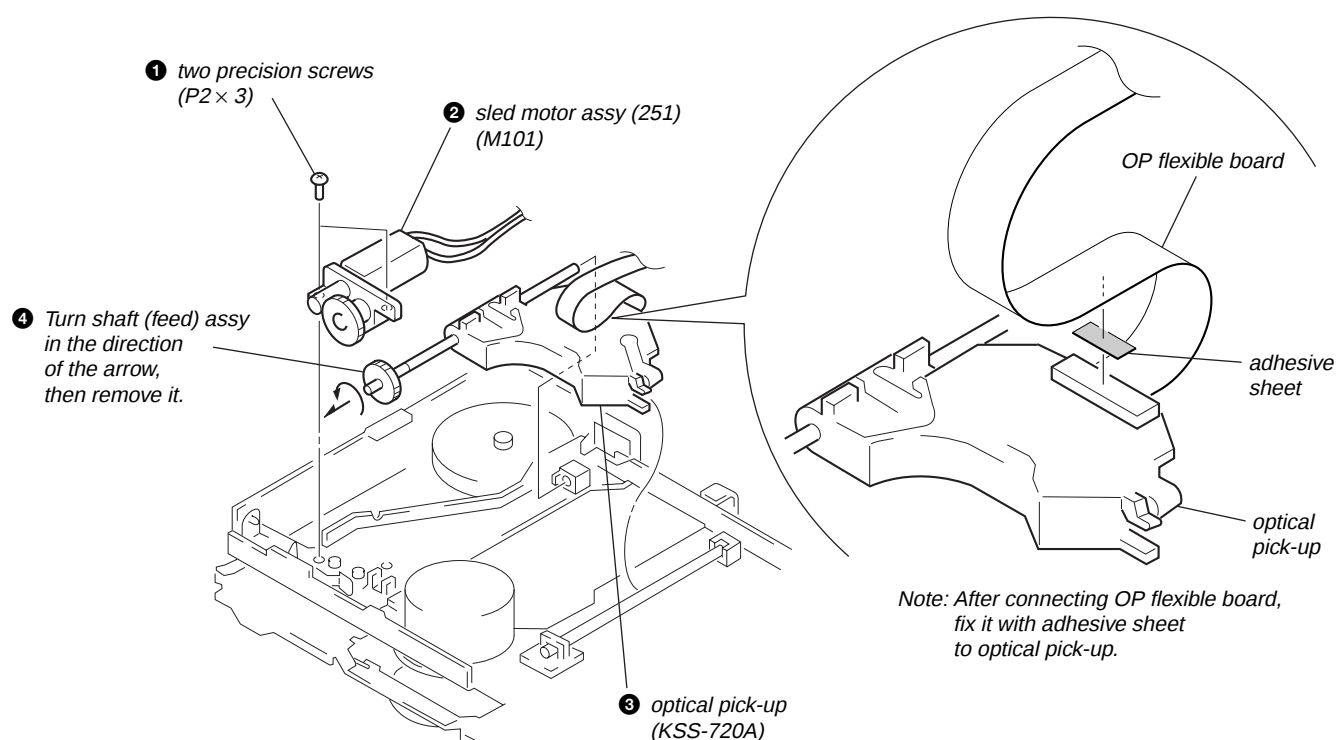
2-9. CHASSIS ASSY



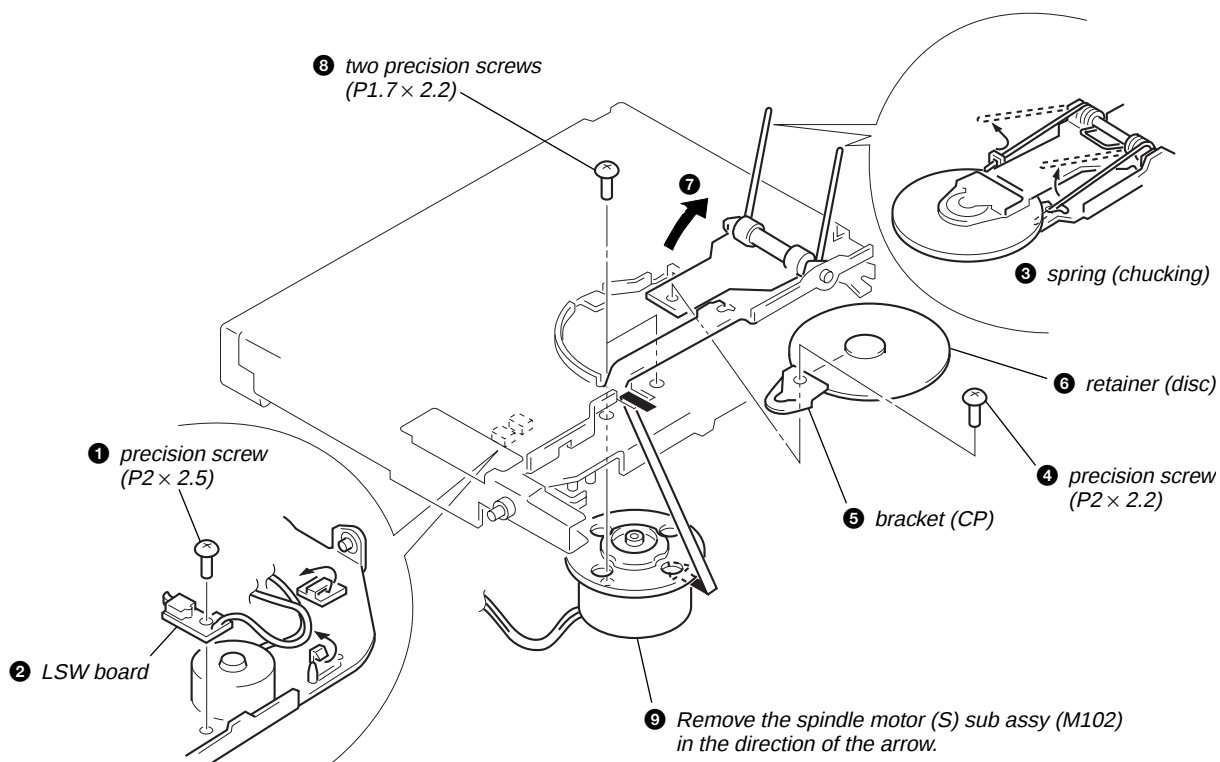
2-10. RF BOARD



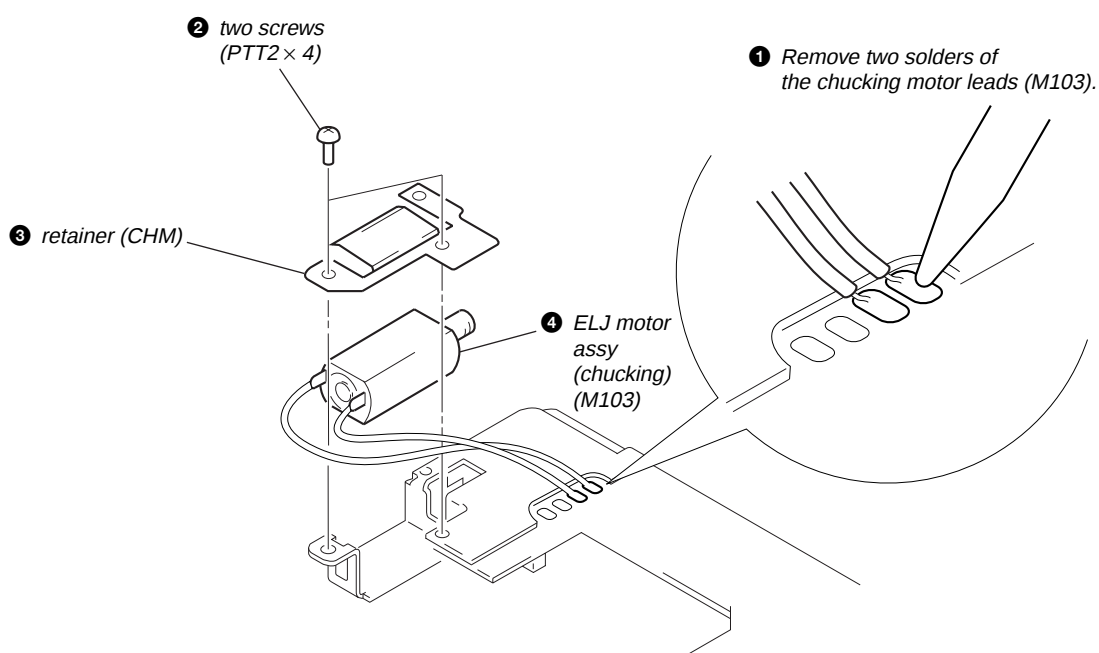
2-11. SLED MOTOR ASSY (251) (M101), OPTICAL PICK-UP (KSS-720A)



2-12. LSW BOARD, SPINDLE MOTOR (S) SUB ASSY (M102)



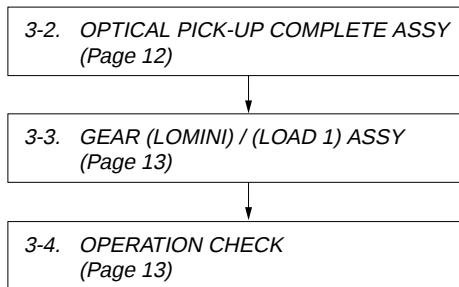
2-13. ELJ MOTOR ASSY (CHUCKING) (M103)



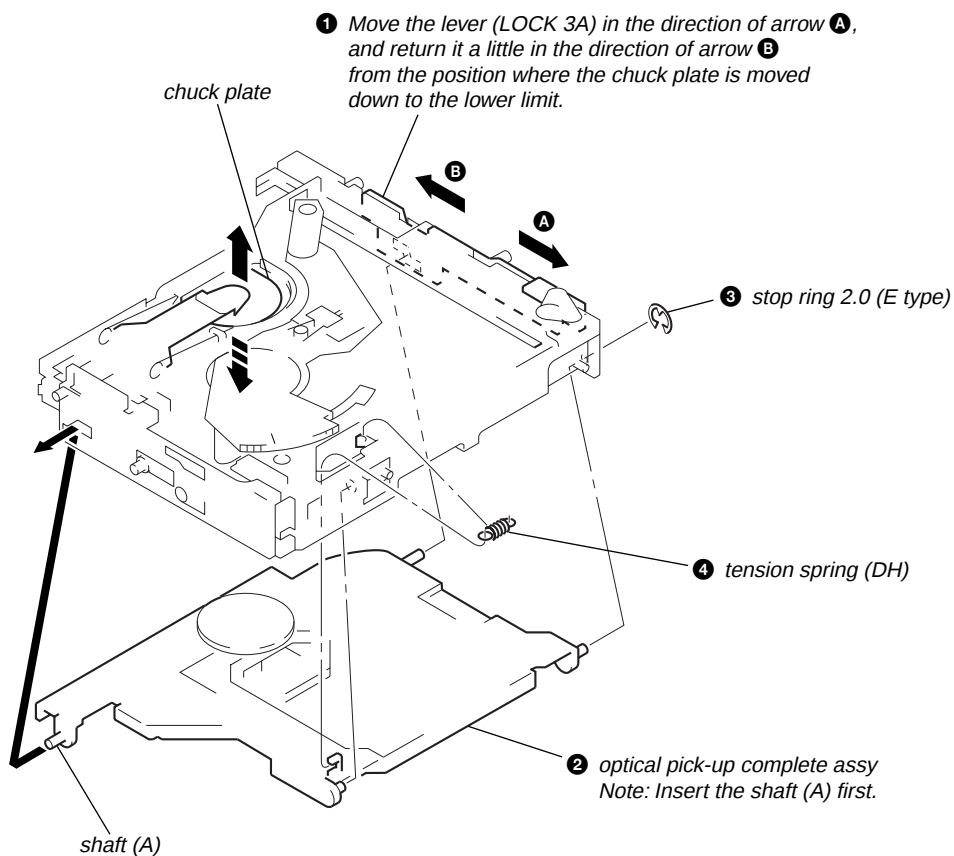
SECTION 3 ASSEMBLY

• This set can be assembled in the order shown below.

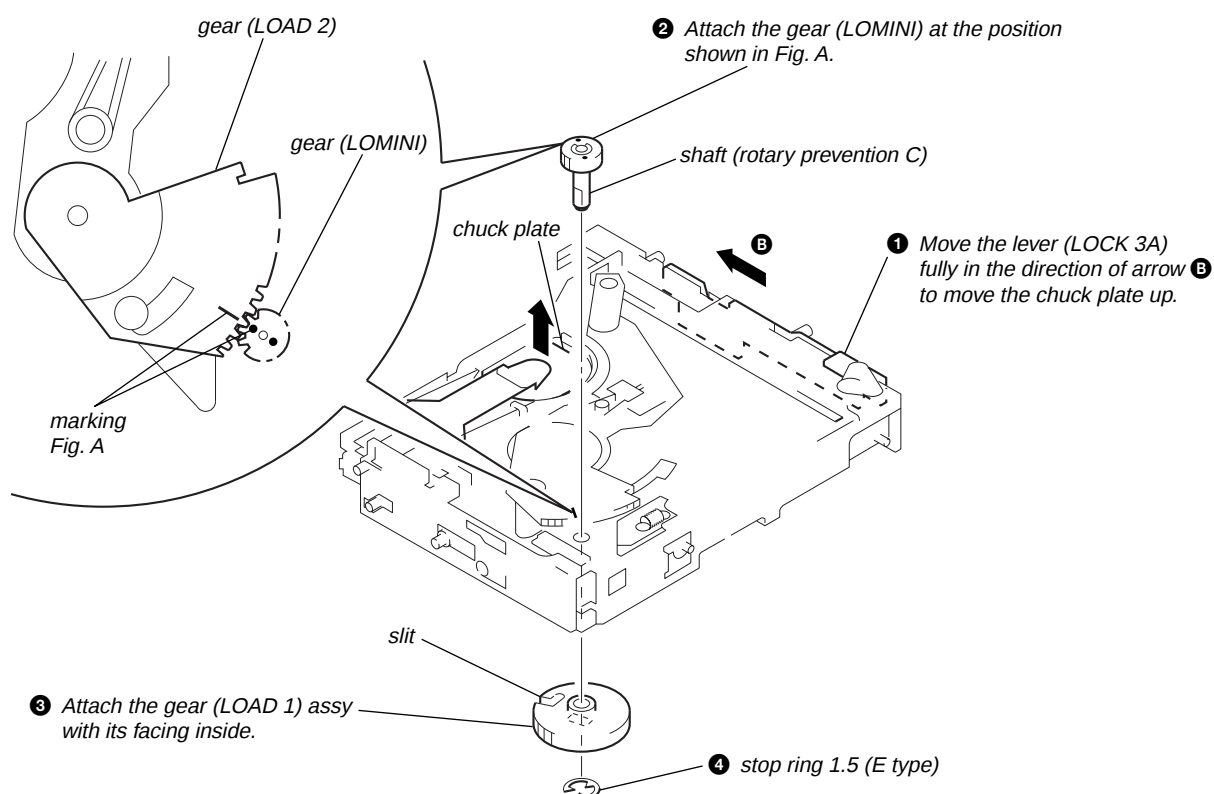
3-1. ASSEMBLY FLOW



3-2. OPTICAL PICK-UP COMPLETE ASSY

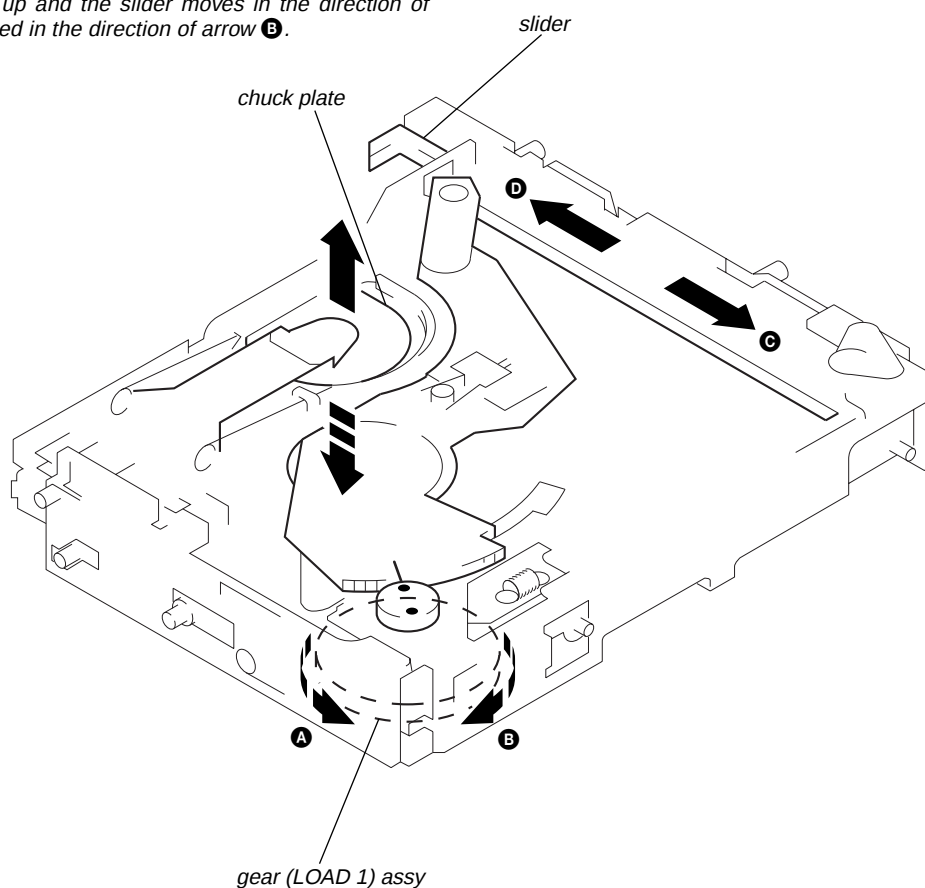


3-3. GEAR (LOMINI)/(LOAD 1) ASSY



3-4. OPERATION CHECK

- 1** Confirm that the slider moves in the direction of arrow **C** to move down the chuck plate if the gear (LOAD 1) is rotated in the direction of arrow **A** or the chuck plate moves up and the slider moves in the direction of arrow **D** if the gear is rotated in the direction of arrow **B**.



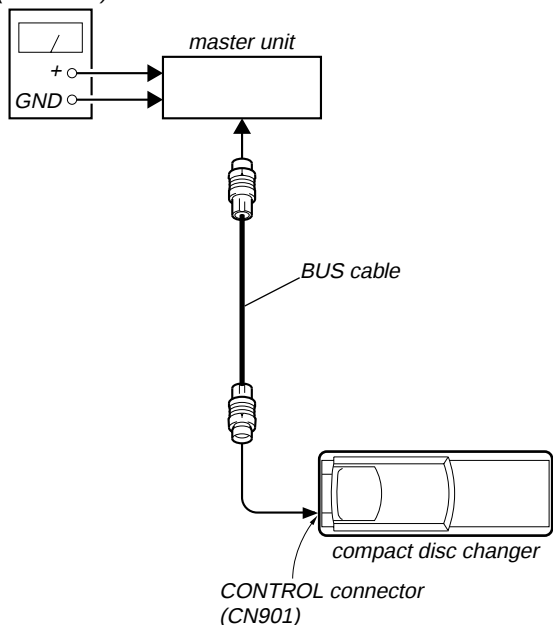
SECTION 4 MECHANICAL ADJUSTMENT

• Elevator Height (Address) Adjustment

Note: This adjustments is necessary when the system controller (IC201), variable resistor (RV201), slider (R), slider (L), or chassis (ELV) was replaced for any repair.

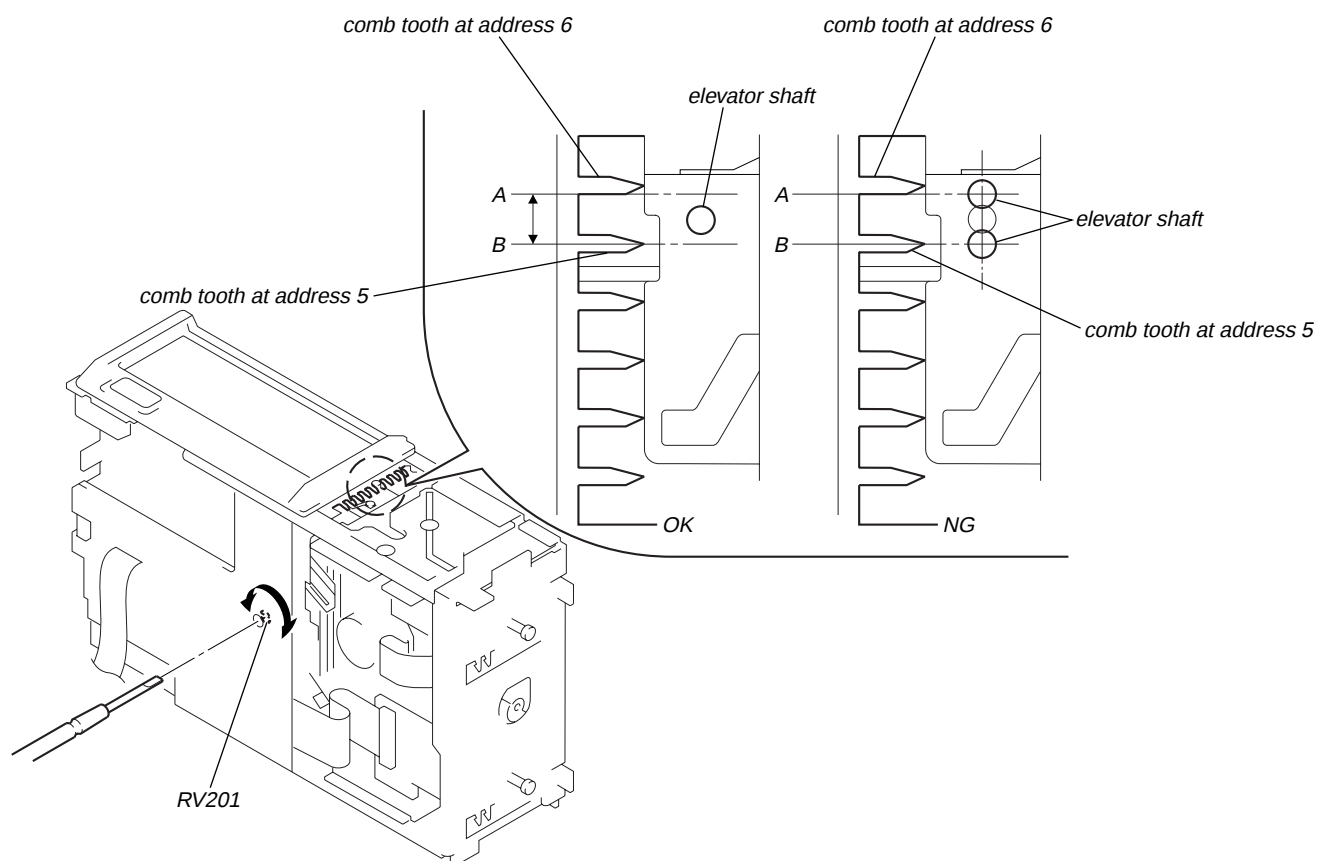
Connection:

power supply
(DC 14.4 V)



Adjustment Method:

1. Connect this set to the master unit (e.g. MDX-C7970/C7970R), load a disc magazine, and place the set vertically as shown below.
2. Connect the regulated power supply to the master unit, and turn the power on.
3. Press the DISC button on the master unit and select DISC 5.
4. At this time, if the elevator shaft does not position between comb teeth A and B at addresses 5 and 6 as shown below, adjust the following.
5. Press repeatedly the DISC + and – buttons on the master unit so that the elevator shafts moves from address 6 to address 5, or from 5 to 6. At this time, adjust RV201 on the main board so that the elevator shaft positions smoothly between comb teeth A and B.
6. Further, place the set horizontally and make same adjustment as mentioned above.
7. After adjustment at addresses 5 to 6 is finished, check all operations from addresses 1 to 10 with the set placed vertically and horizontally respectively to confirm that the elevator shaft positions in a range between comb teeth A to B.

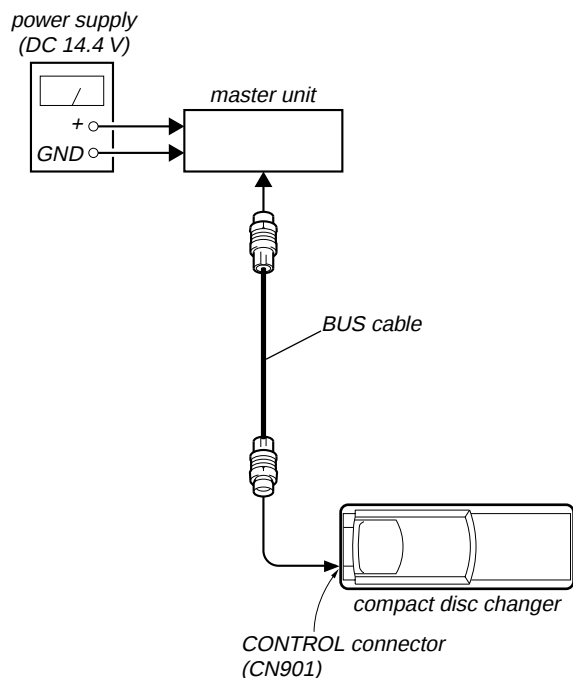


SECTION 5 ELECTRICAL CHECK

Note:

1. This check is performed with the set placed horizontally.
2. Power supply voltage: DC14.4 V (more than 3 A).
3. Be sure to use the disc "YEDS-18" parts code: 3-702-101-01, but only when indicated.

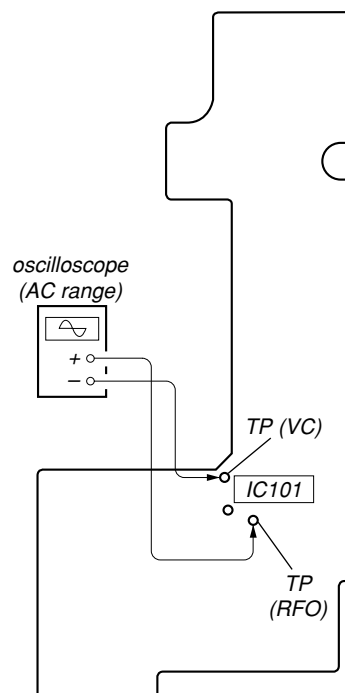
Connection:



Focus Bias Check

Connection:

– RF Board (Component Side) –



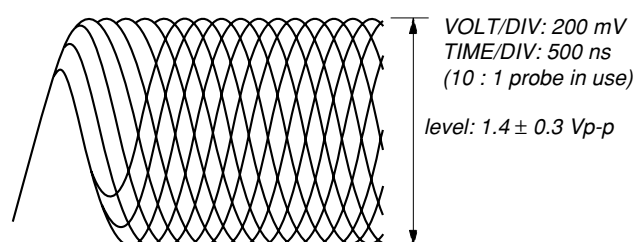
Procedure:

1. Connect the oscilloscope to TP (RFO) and TP (VC) on the RF board.
2. Put the set into play mode by loading the disc (YEDS-18).
3. Confirm that oscilloscope waveform is clear and check RF signal level is correct or not.

Note:

Clear RF signal waveform means that the shape "◇" can be clearly distinguished at the center of the waveform.

RF signal waveform

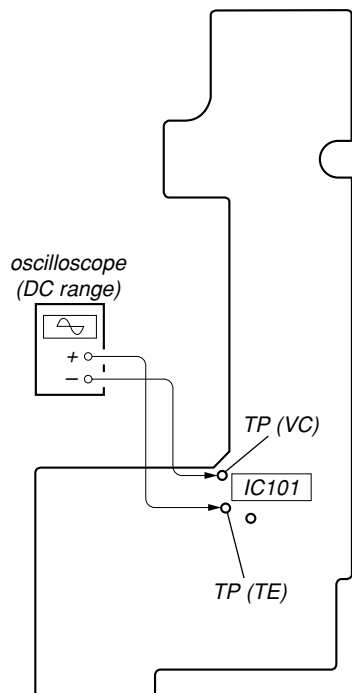


When observing the eye pattern, set the oscilloscope to AC range and raise the vertical sensitivity so that it may be easily seen.

Tracking Offset Check

Connection:

– RF Board (Component Side) –

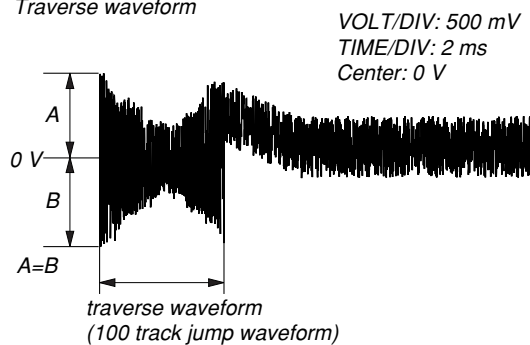


Procedure:

1. Connect the oscilloscope to TP (TE) and TP (VC) on the RF board.
2. Put the set into play mode by loading the disc (YEDS-18).
3. Press the , buttons on the master unit, and check the traverse waveform*.
4. Confirm that the oscilloscope waveform is symmetrical on the top and bottom in relation to 0 V dc, and check this level.

* Traverse waveform: This is the tracking error wave form appears when crossing the track.

Traverse waveform



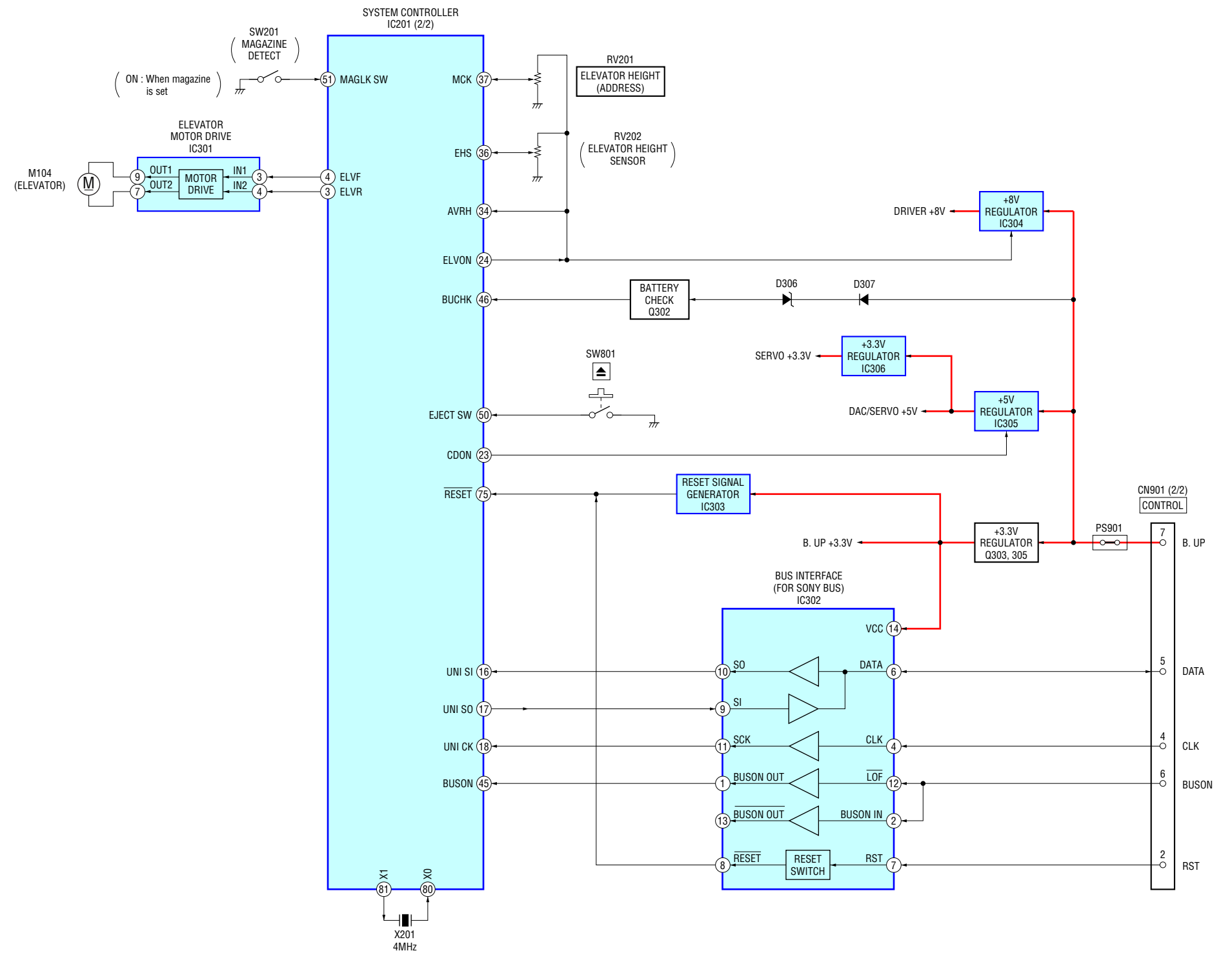
Legend:

- Red Arrow: SIGNAL PATH
- Red Double Arrow: CD PLAY

Key Components and Connections:

- OPTICAL PICK-UP BLOCK (KSS-720A):** Includes LASER DIODE, PD, LD, and 2-AXIS DEVICE (TRACKING, FOCUS).
- IC101: RF AMP, FOCUS/TRACKING ERROR AMP, DIGITAL SIGNAL PROCESSOR, DIGITAL SERVO PROCESSOR, DIGITAL FILTER, D/A CONVERTER.**
 - Inputs: RFAC (15), RFDC (28), FE (16), TE (18), SW (12), PD (2), LD (1), LD (1).
 - Outputs: RFAC (15), RFDC (28), FE (16), TE (18), SW (12), PD (2), LD (1), LD (1).
- IC201: TRACKING/FOCUS COIL DRIVE, SLED/SPINDLE/CHUCKING MOTOR DRIVE, SYSTEM CONTROLLER.**
 - Inputs: V03+ (8), V03- (9), V04+ (6), V04- (7), V02+ (10), V02- (11), V01+ (12), V01- (13), VLO+ (5), VLO- (4).
 - Outputs: VIN3+ (25), VIN3- (24), VIN4+ (32), VIN4- (31), VIN2+ (22), VIN2- (21), VIN1-B (18), FWD (1), REV (2).
- Other Components:**
 - GROUND-ISOLATION IC401:** AOUT1 (70), AOUT2 (77), AIN1 (71), AIN2 (76), LOUT1 (72), LOUT2 (75).
 - MUTING CONTROL SWITCH Q402:** MUTE (67).
 - CD-ROM/RW SELECT SWITCH Q202:** RW SEL (99), EMPH (64), GFS (18).
 - SW3 (LIMIT), SW1 (CHUCKING END DETECT), SW2 (SAVE END DETECT):** Connected to LIM SW (98), LOAD SW (97), and SAVE SW (96).

6-2. BLOCK DIAGRAM – BUS CONTROL/POWER SUPPLY Section –



6-3. NOTE FOR PRINTED WIRING BOARDS AND SCHEMATIC DIAGRAMS

Note on Printed Wiring Board:

- : parts extracted from the component side.
 - : parts extracted from the conductor side.
 - △ : internal component.
 - : Pattern from the side which enables seeing.
- (The other layers' patterns are not indicated.)

Caution:
Pattern face side: Parts on the pattern face side seen from the pattern face are indicated.
Parts face side: Parts on the parts face side seen from the parts face are indicated.

Note on Schematic Diagram:

- All capacitors are in μF unless otherwise noted. pF : μF
- 50 WV or less are not indicated except for electrolytics and tantalums.
- All resistors are in Ω and $\frac{1}{4}W$ or less unless otherwise specified.
- △ : internal component.
- : panel designation.

Note:

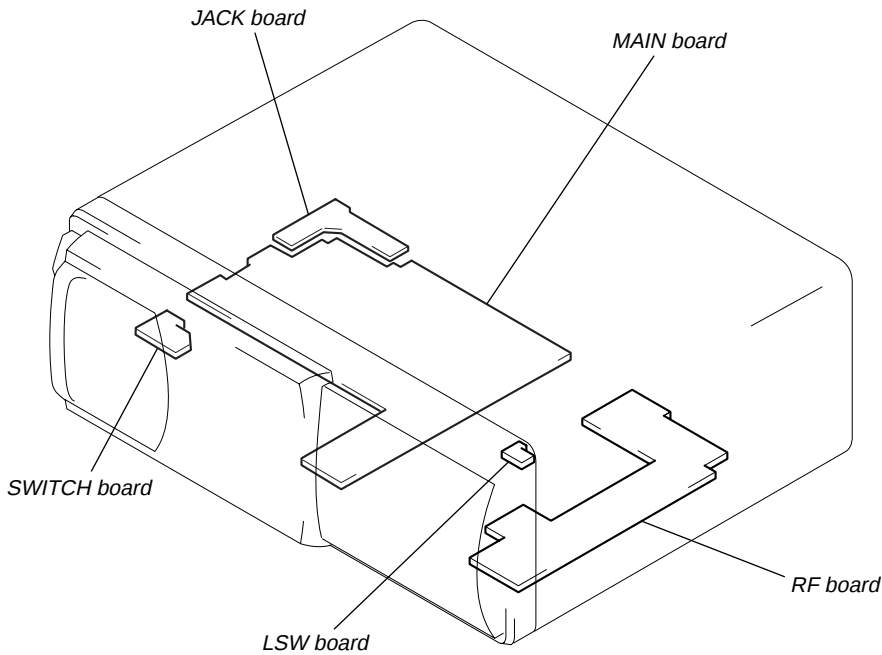
The components identified by mark △ or dotted line with mark △ are critical for safety. Replace only with part number specified.

Note:

Les composants identifiés par une marque △ sont critiques pour la sécurité. Ne les remplacer que par une pièce portant le numéro spécifié.

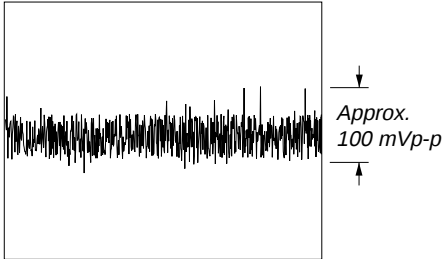
- : B+ Line.
- : adjustment for repair.
- Power voltage is dc 14.4V and fed with regulated dc power supply from CD changer controller.
- Voltages and waveforms are dc with respect to ground under no-signal conditions.
- no mark : CD PLAY
- Voltages are taken with a VOM (Input impedance 10 M Ω). Voltage variations may be noted due to normal production tolerances.
- Waveforms are taken with a oscilloscope. Voltage variations may be noted due to normal production tolerances.
- Circled numbers refer to waveforms.
- Signal path.
- ⇒ : CD PLAY

• Circuit Boards Location

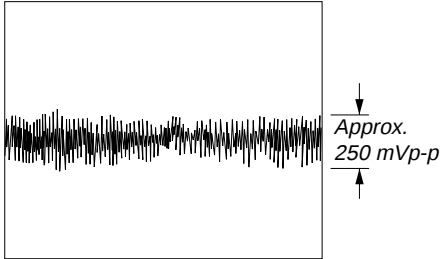


• Waveforms
– RF Board –

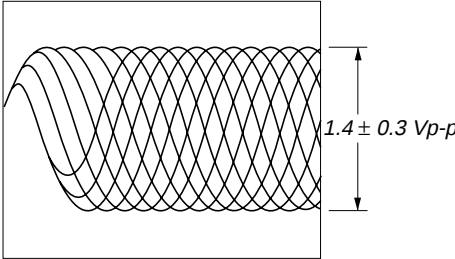
① IC101 ⑩ (FE) (CD play mode)



② IC101 ⑩ (TE) (CD play mode)

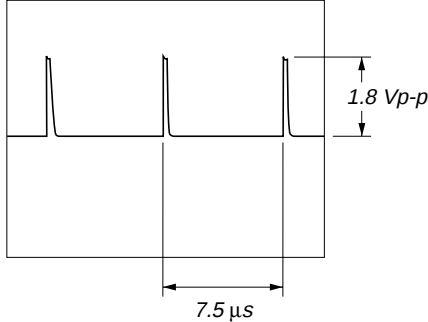


③ IC101 ⑩ (RFAC) (CD play mode)

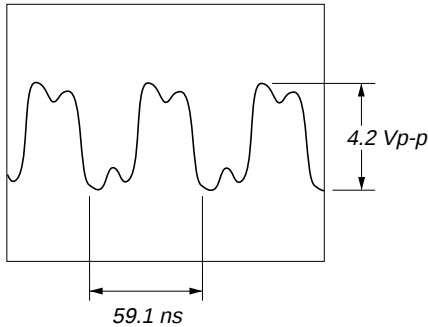


– MAIN Board –

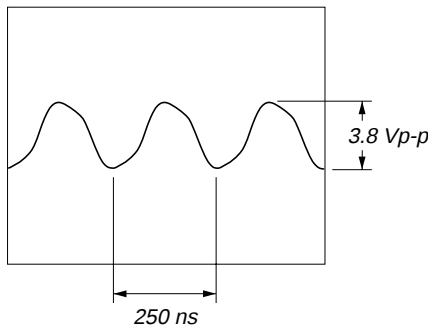
① IC101 ②⑥ (MDP) (CD play mode)



② IC101 ⑦⑦ (XTAO) (CD play mode)

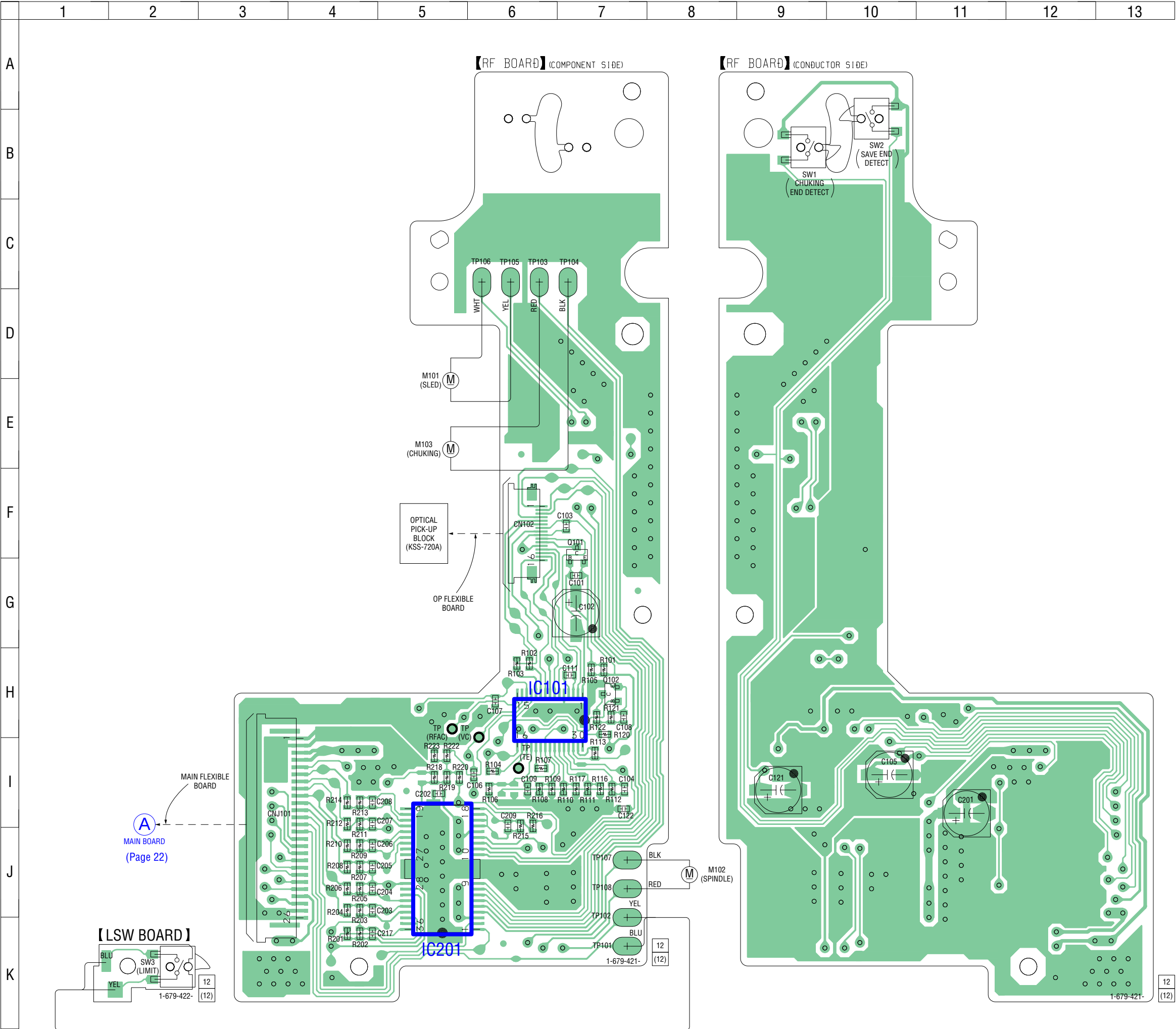


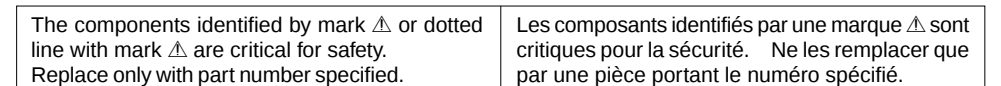
③ IC201 ⑧① (X1) (CD play mode)



• Semiconductor Location

Ref. No.	Location
IC101	H-6
IC201	J-5
Q101	F-7
Q102	H-7

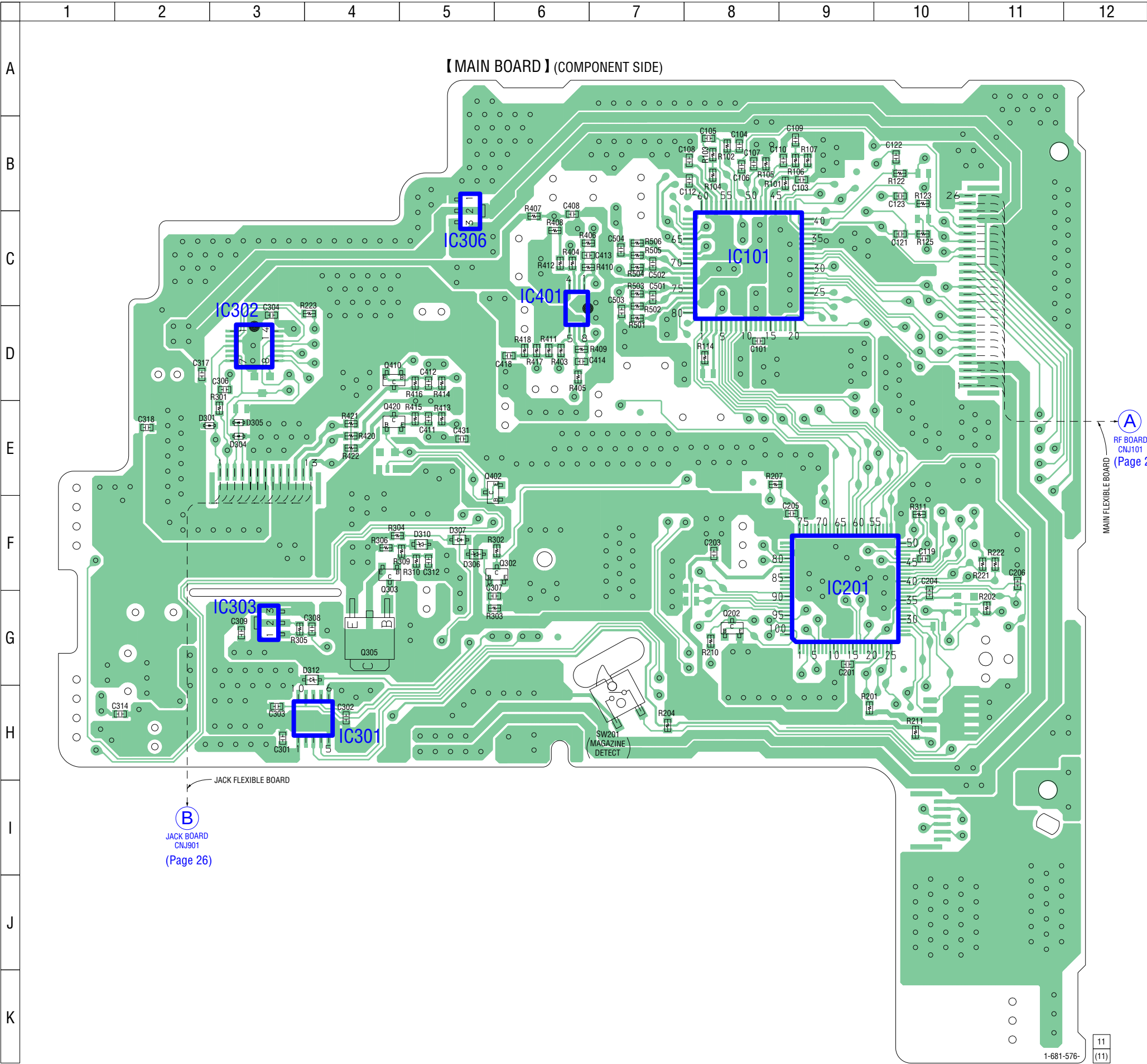




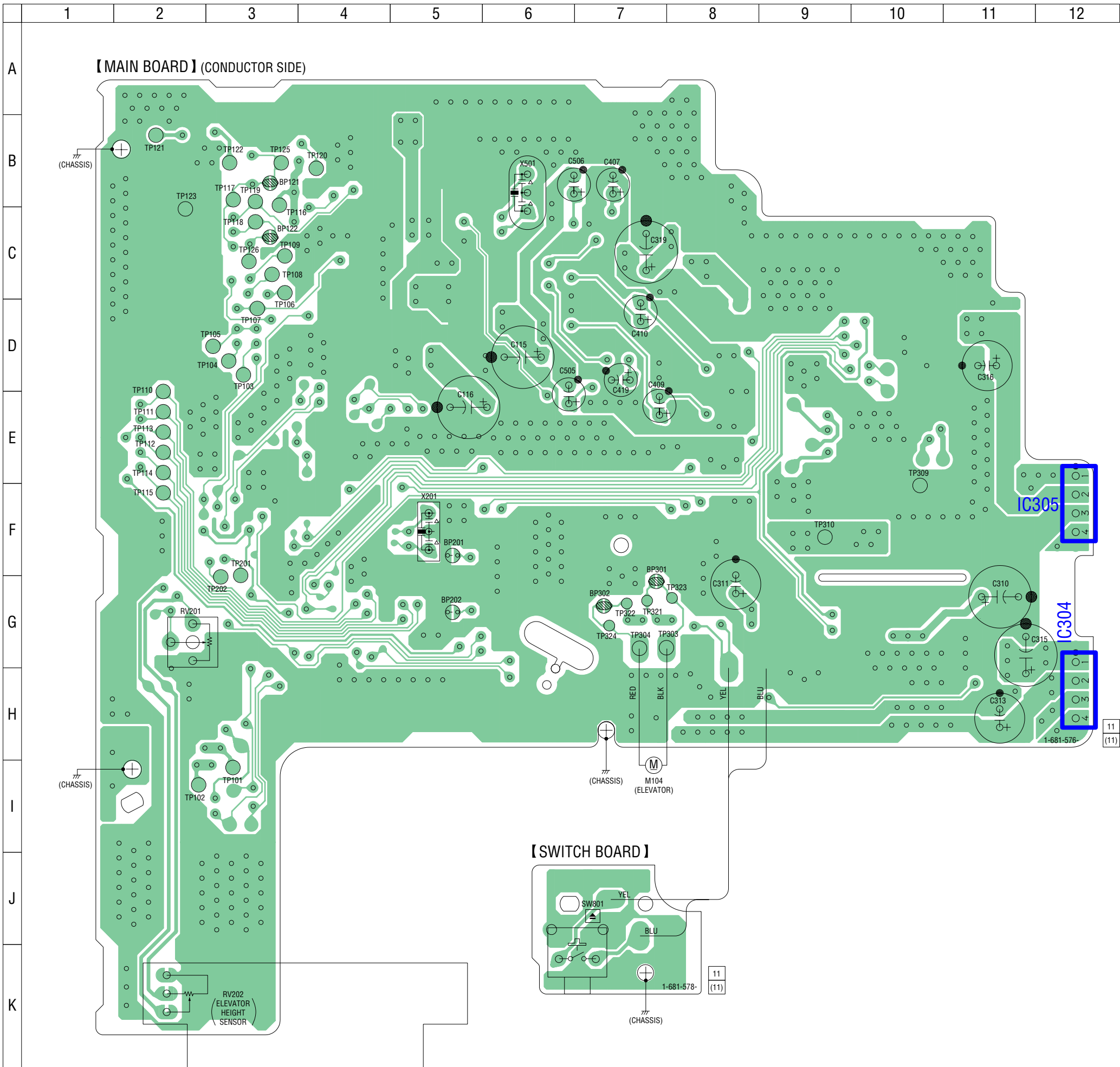
6-6. PRINTED WIRING BOARDS – MAIN Board (Component Side) –

• Semiconductor Location

Ref. No.	Location
D301	E-2
D304	E-3
D305	E-3
D306	F-5
D307	F-5
D310	F-5
D312	G-4
IC101	C-8
IC201	F-9
IC301	H-4
IC302	D-3
IC303	G-3
IC306	C-5
IC401	C-6
Q202	G-8
Q302	F-6
Q303	F-4
Q305	G-4
Q402	F-6
Q410	D-4
Q420	E-4



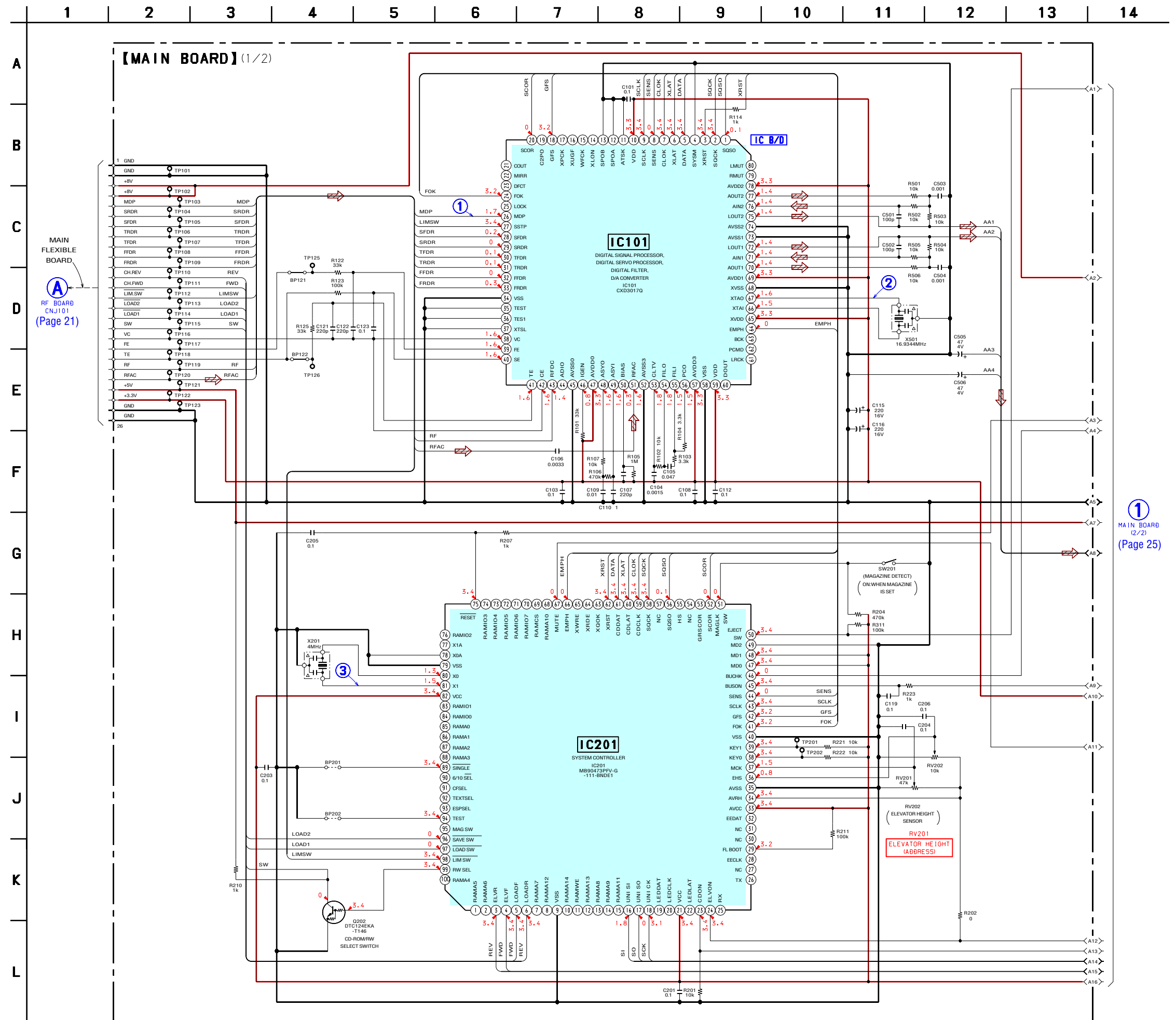
6-7. PRINTED WIRING BOARDS – MAIN (Conductor Side)/SWITCH Boards –



• Semiconductor Location

Ref. No.	Location
IC304	H-12
IC305	F-12

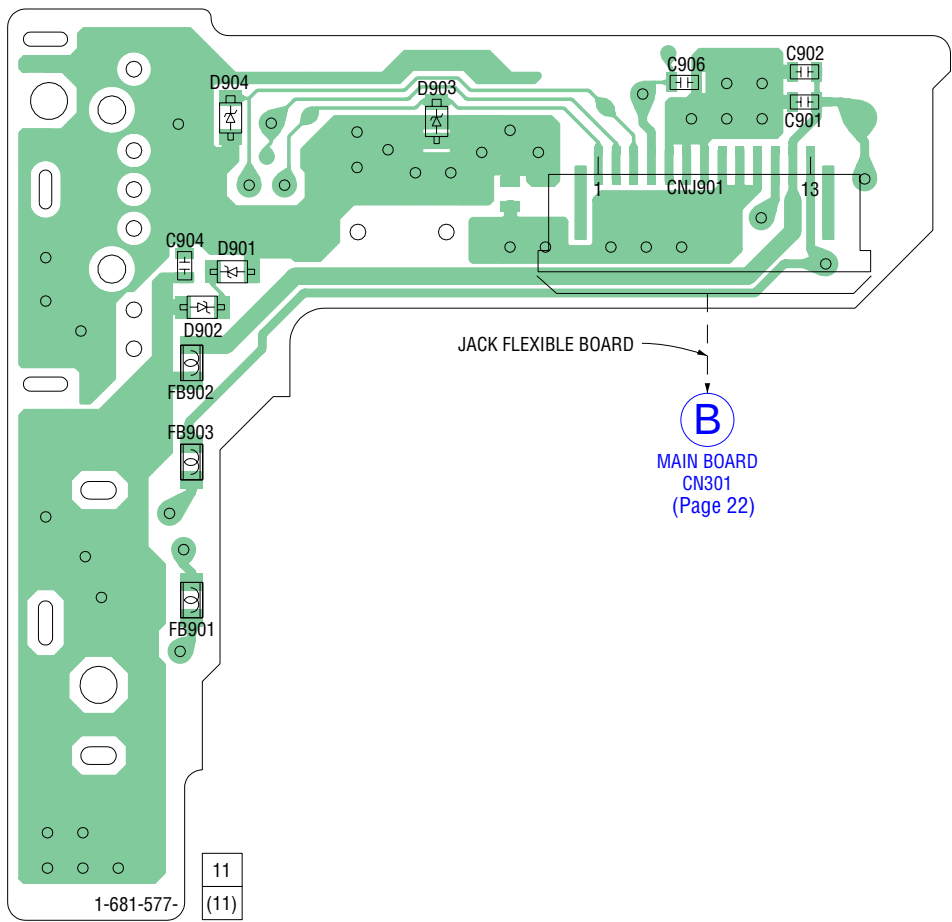
6-8. SCHEMATIC DIAGRAM – MAIN Board (1/2) – • See page 19 for for Waveforms. • See page 27 for IC Block Diagram.



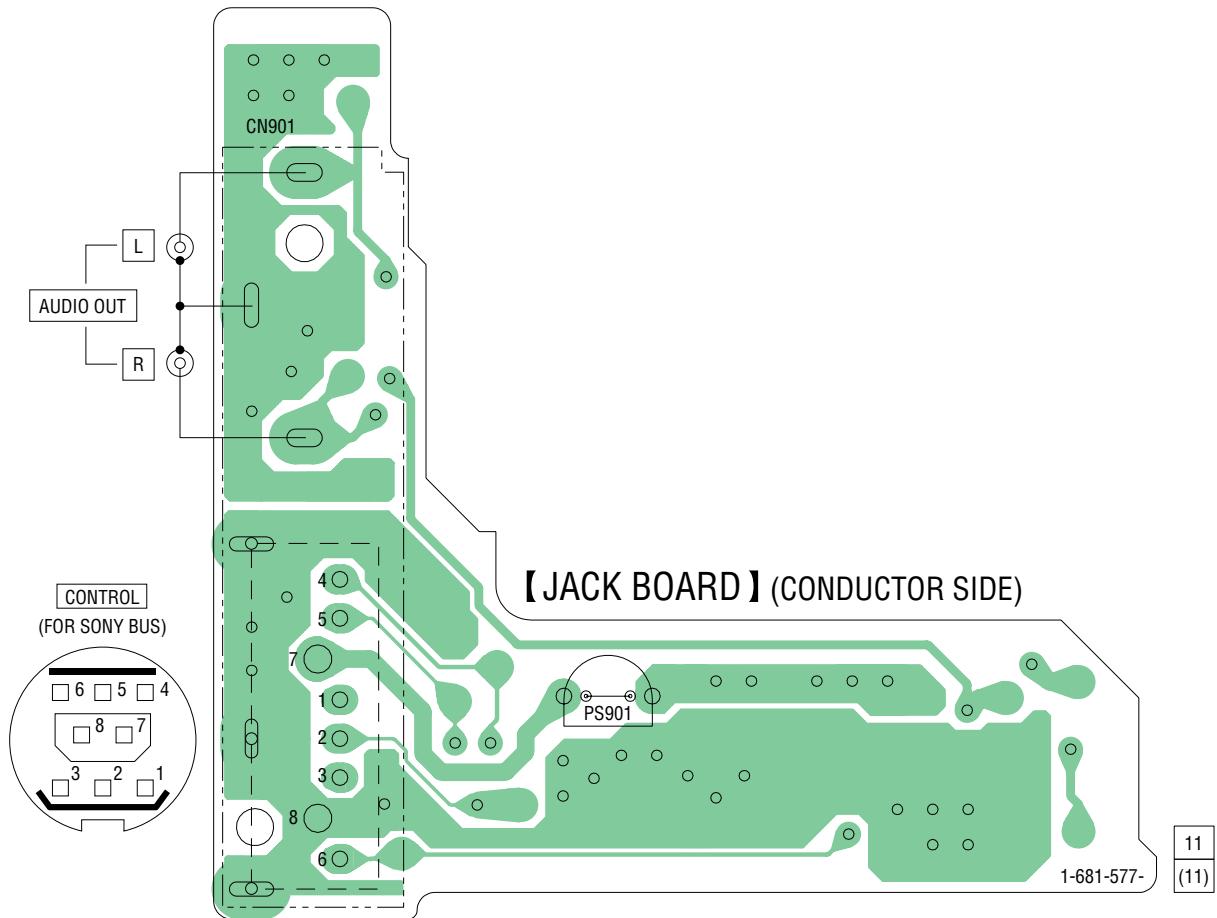
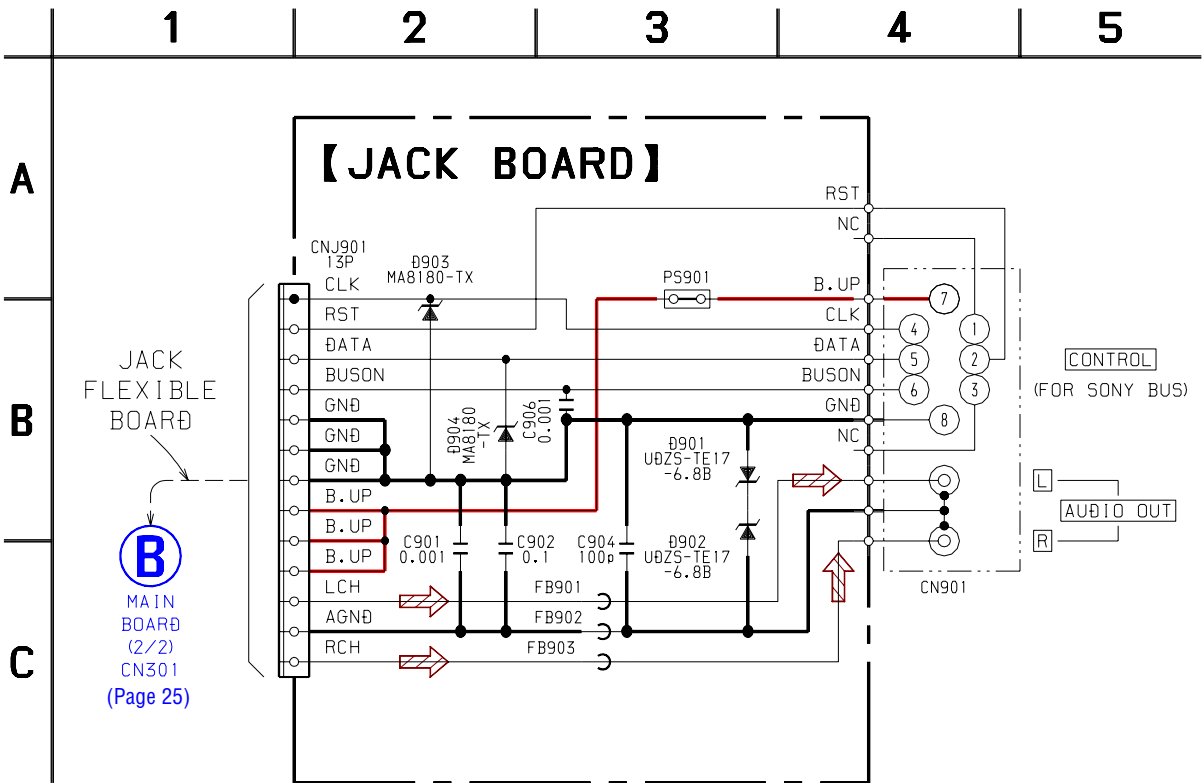


6-10. PRINTED WIRING BOARDS – JACK Board –

【 JACK BOARD 】 (COMPONENT SIDE)

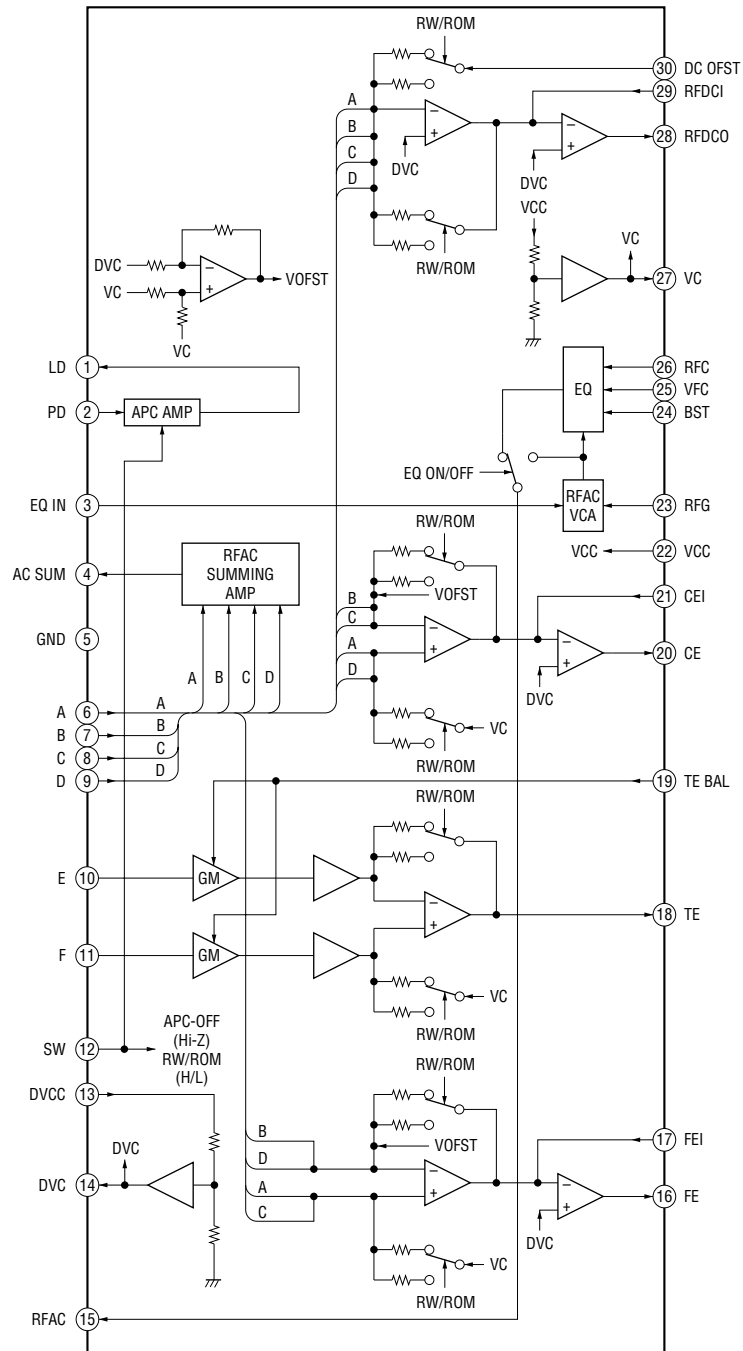


6-11. SCHEMATIC DIAGRAM – JACK Board –

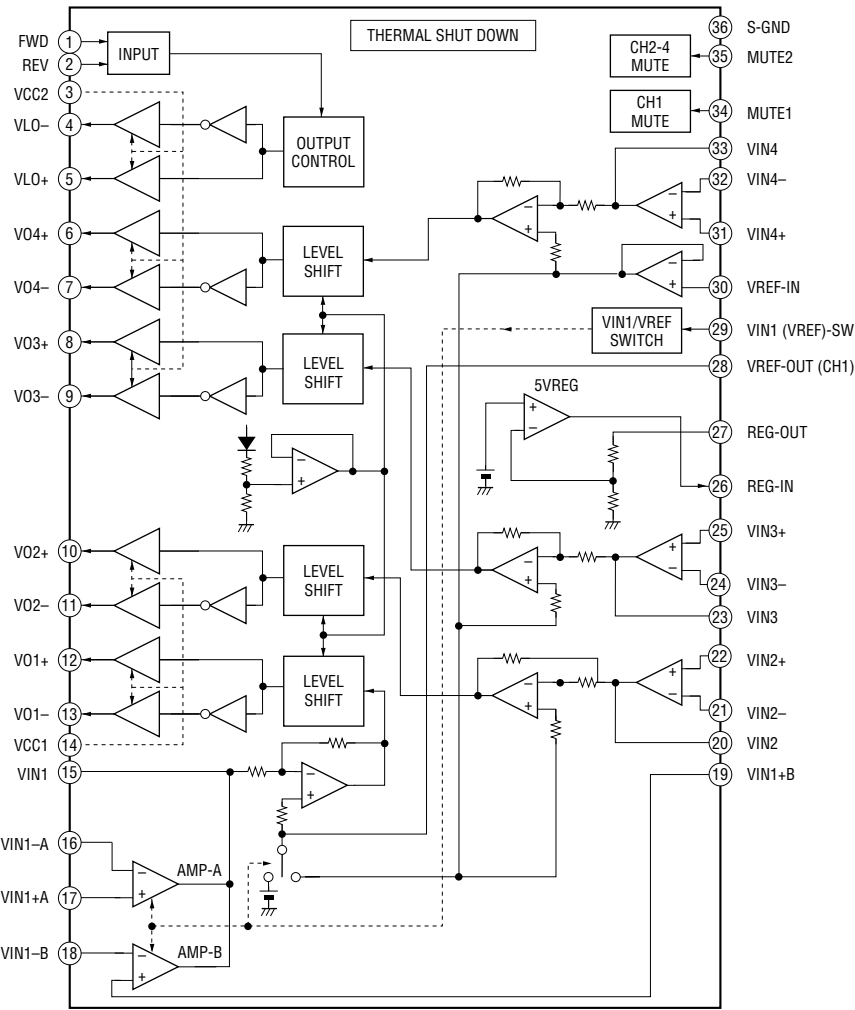


• IC Block Diagrams
– RF Board –

IC101 CXA2581N-T4

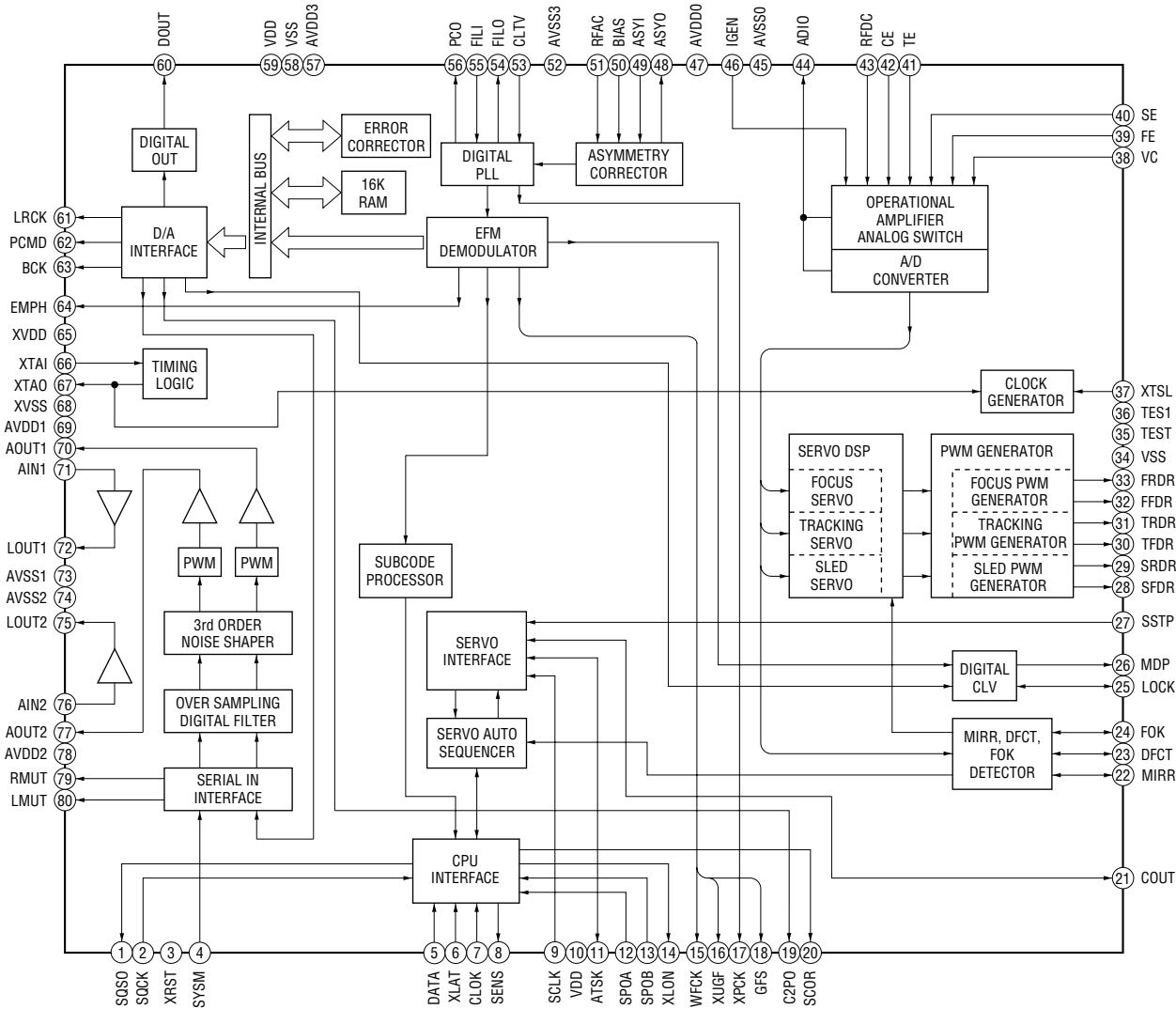


IC201 LA6576L-TE-L

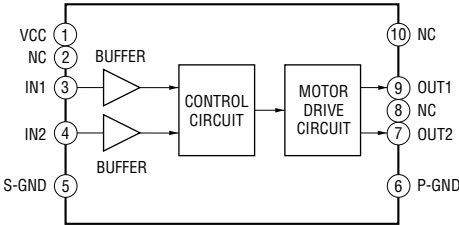


- MAIN Board -

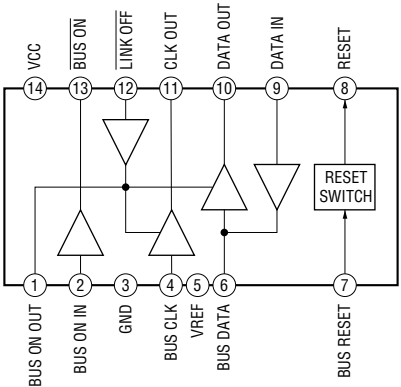
IC101 CXD3017Q



IC301 LB1930M-TLM

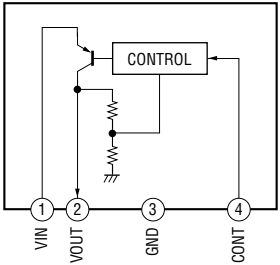


IC302 BA8272AFV-E2



IC304 NJM2395AF08

IC305 NJM2395AF05



6-12. IC PIN FUNCTION DESCRIPTION

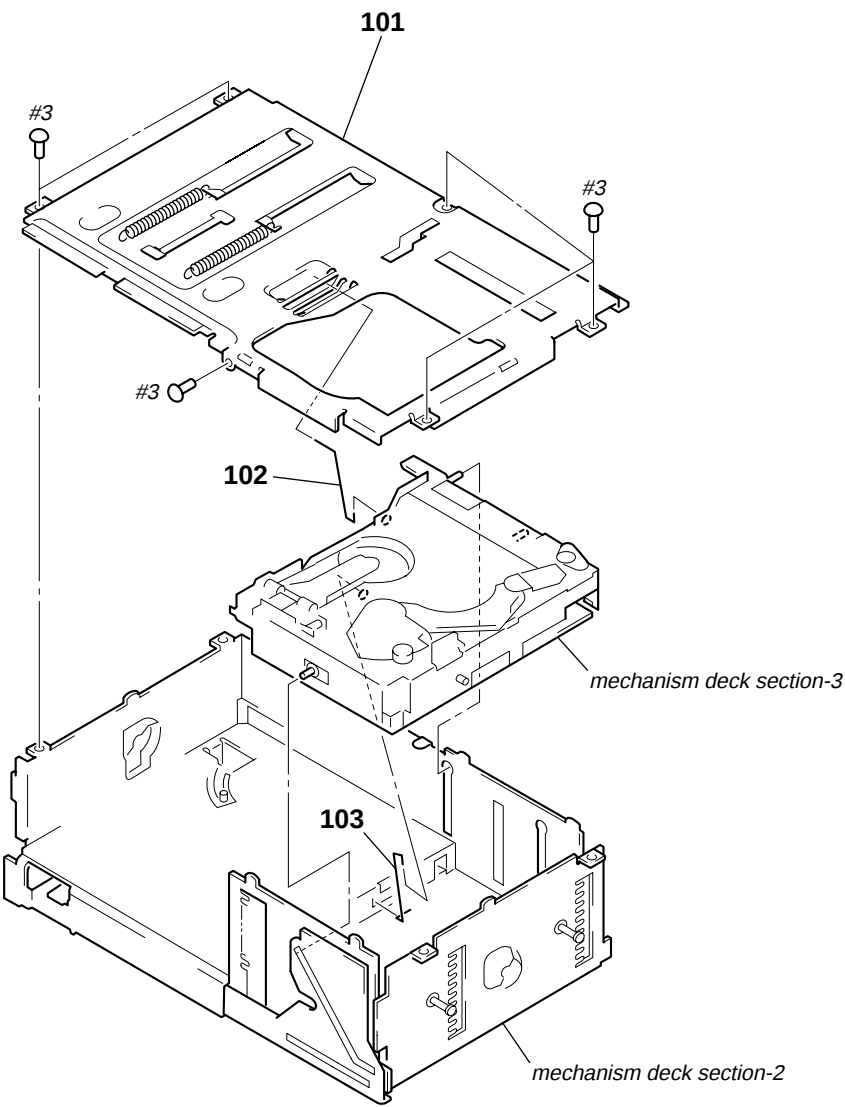
• MAIN BOARD IC201 MB90473PFV-G-111-BNDE1 (SYSTEM CONTROLLER)

Pin No.	Pin Name	I/O	Description
1, 2	RAMA5, RAMA6	O	Address signal output terminal Not used
3	ELVR	O	Motor drive signal (elevator down direction) output
4	ELVF	O	Motor drive signal (elevator up direction) output
5	LOADF	O	Motor drive signal (load chucking direction) output
6	LOADR	O	Motor drive signal (save direction) output
7, 8	RAMA7, RAMA12	O	Address signal output terminal Not used
9	VSS	—	Ground terminal
10	RAMA14	O	Address signal output terminal Not used
11	RAMWE	O	Write enable output terminal Not used
12 to 15	RAMA13, RAMA8, RAMA9, RAMA11	O	Address signal output terminal Not used
16	UNI SI	I	Serial data input from the SONY bus interface
17	UNI SO	O	Serial data output to the SONY bus interface
18	UNI CK	I	Serial data transfer clock signal input from the SONY bus interface
19	LEDDAT	O	Not used
20	LEDCLK	O	Not used
21	VCC	—	Power supply terminal (+3.3V)
22	LEDLAT	O	Not used
23	CDON	O	D/A converter and servo section power supply on/off control signal output “H”: power on
24	ELVON	O	Mechanism deck section power supply on/off control signal output “H”: power on
25	RX	I	Input terminal at the flash memory data write mode Not used
26	TX	O	Output terminal at the flash memory data write mode Not used
27	NC	O	Not used
28	EECLK	O	Serial data transfer clock signal output to the EEPROM Not used
29	FL BOOT	I	Flash memory data write control signal input terminal “L” active Not used
30, 31	NC	O	Not used
32	EEDAT	I/O	Two-way data bus with the EEPROM Not used
33	AVCC	—	Power supply terminal (+3.3V) (for A/D converter)
34	AVRH	I	Reference voltage (+3.3V) input terminal (for A/D converter)
35	AVSS	—	Ground terminal (for A/D converter)
36	EHS	I	Elevator height position detection signal input from the elevator height sensor (A/D input)
37	MCK	I	Input of detection signal for the fine adjustment (elevator height (address) adjustment) of elevator height position (A/D input)
38, 39	KEY0, KEY1	I	Not used
40	VSS	—	Ground terminal
41	FOK	I	Focus OK signal input “H”: OK
42	GFS	I	Guard frame sync signal input “H”: OK
43	SCLK	O	Serial data reading clock signal output to the CXD3017Q
44	SENS	I	Internal status signal (sense signal) input
45	BUSON	I	Bus on/off control signal input from the SONY bus interface “H”: bus on
46	BUCHK	I	Battery detection signal input “L”: battery on
47, 48	MD0, MD1	I	Setting terminal for the CPU operational mode (fixed at “H” in this set)
49	MD2	I	Setting terminal for the CPU operational mode (fixed at “L” in this set)
50	EJECT SW	I	Eject switch input terminal “L” active
51	MAGLK SW	I	Magazine detect switch input terminal “L”: magazine is set

Pin No.	Pin Name	I/O	Description
52	SCOR	I	Subcode sync (S0+S1) detection signal input from the CXD3017Q
53	GRSCOR	I	Subcode sync (S0+S1) detection signal input terminal Not used
54	NC	O	Not used
55	HS	O	Normal/high speed playback control signal output terminal “L”: high speed playback Not used
56	SQSO	I	Subcode Q data input from the CXD3017Q
57	NC	O	Not used
58	SQCK	O	Subcode Q data reading clock signal output to the CXD3017Q
59	CDCLK	O	Serial data transfer clock signal output to the CXD3017Q
60	CDLAT	O	Serial data latch pulse signal output to the CXD3017Q
61	CDDAT	O	Serial data output to the CXD3017Q
62	XRST	O	System reset signal output to the CXD3017Q “L”: reset
63	XQOK	O	Subcode Q OK pulse signal output terminal Not used
64	XRDE	O	D-RAM read enable signal output terminal Not used
65	XWRE	O	D-RAM write enable signal output terminal Not used
66	EMPH	O	Emphasis control signal output “H”: emphasis on
67	MUTE	O	Audio line muting on/off control signal output “H”: muting on
68	RAMA10	O	Address signal output terminal Not used
69	RAMCS	O	Chip select enable output terminal Not used
70 to 74	RAMIO7 to RAMIO3	I/O	Two-way data bus terminal Not used
75	$\overline{\text{RESET}}$	I	System reset signal input from the SONY bus interface and reset signal generator “L”: reset For several hundreds msec. after the power supply rises, “L” is input, then it changes to “H”
76	RAMIO2	I/O	Two-way data bus terminal Not used
77	X1A	O	Sub system clock output terminal Not used
78	X0A	I	Sub system clock input terminal Not used
79	VSS	—	Ground terminal
80	X0	I	Main system clock input terminal (4 MHz)
81	X1	O	Main system clock output terminal (4 MHz)
82	VCC	—	Power supply terminal (+3.3V)
83, 84	RAMIO1, RAMIO0	I/O	Two-way data bus terminal Not used
85 to 88	RAMA0 to RAMA3	O	Address signal output terminal Not used
89	$\overline{\text{SINGLE}}$	I	Setting terminal for the single disc/multiple discs mode “L”: single disc mode, “H”: multiple discs mode fixed at “H”
90	6/10 SEL	I	Setting terminal for the 6 discs changer/10 discs changer model “L”: 10 discs changer model, “H”: 6 discs changer model Not used
91	CFSEL	I	Custom file on/off setting terminal “L”: custom file on fixed at “H”
92	TEXTSEL	I	CD text mode setting terminal “L”: CD text on, “H”: does not display track name fixed at “H”
93	ESPSEL	I	ESP mode setting terminal “L”: ESP on Not used
94	TEST	I	Test on/off setting terminal “L”: test mode Normally fixed at “H”
95	MAG SW	I	Magazine in/out detect switch input terminal Not used
96	$\overline{\text{SAVE SW}}$	I	Save end detect switch input terminal “L”: When completion of the disc save operation

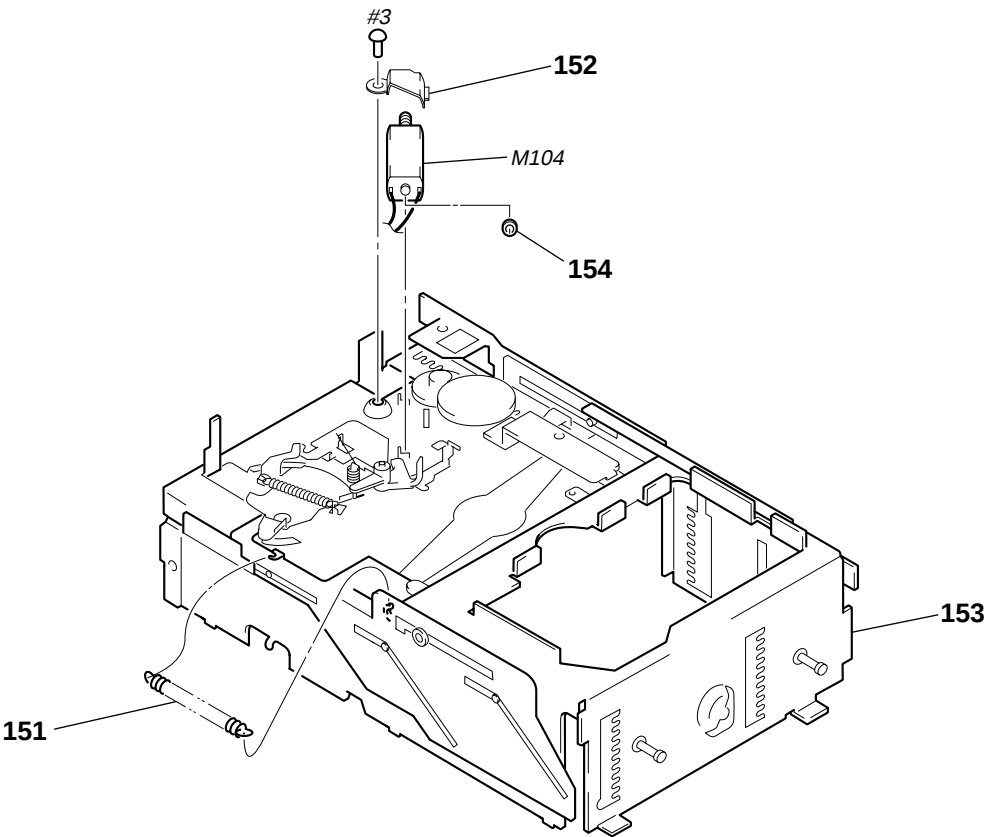
Pin No.	Pin Name	I/O	Description
97	$\overline{\text{LOAD SW}}$	I	Chuckling end detect switch input terminal “L”: When completion of the disc chucking operation
98	$\overline{\text{LIM SW}}$	I	Sled limit in detect switch input terminal “L”: When the optical pick-up is inner position
99	RW SEL	O	CD-ROM/RW selection signal output “L”: CD-RW, “H”: CD-ROM
100	RAMA4	O	Address signal output terminal Not used

7-2. MECHANISM DECK SECTION-1
(MG-251B-137)



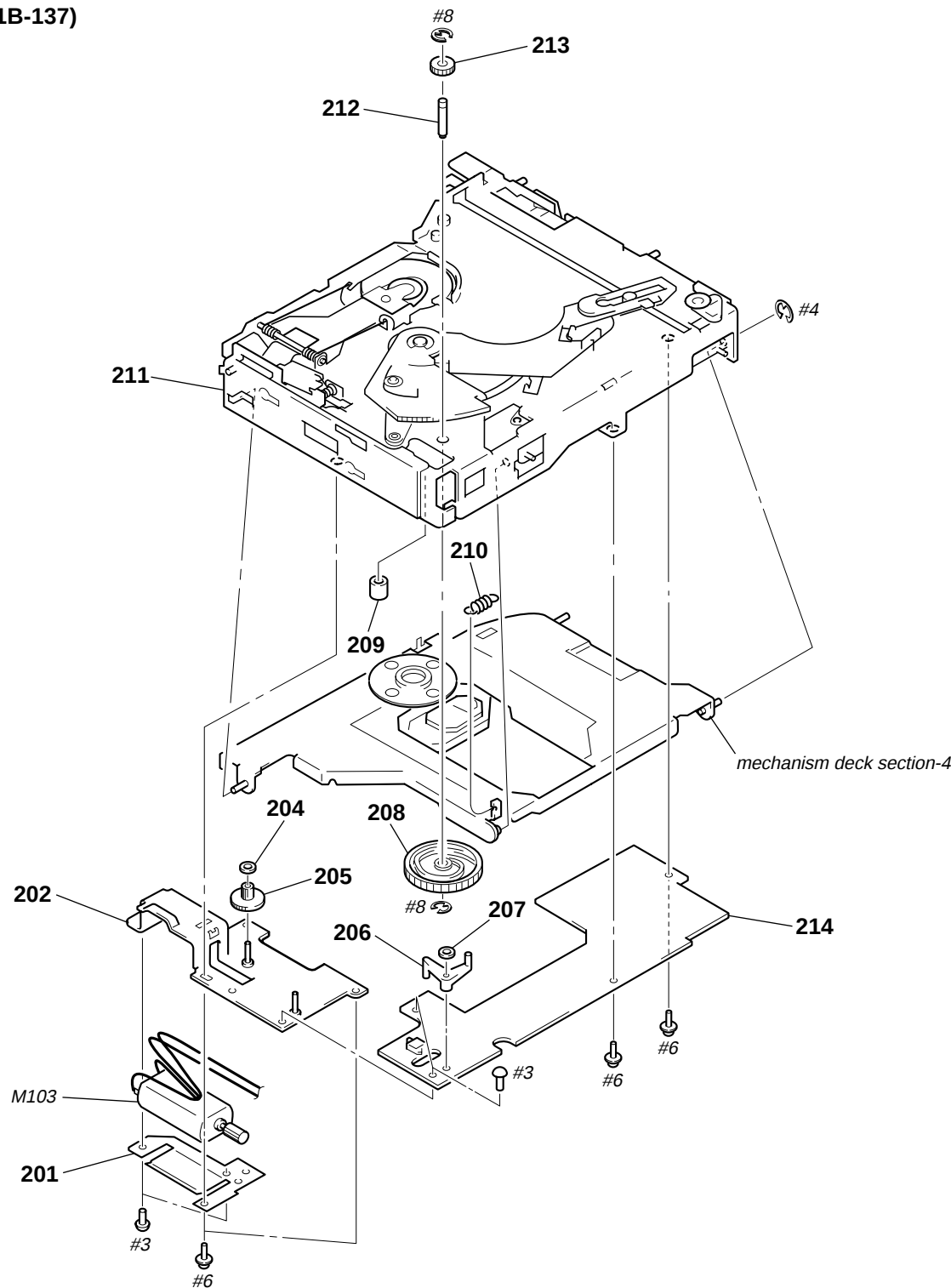
Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
101	X-3378-091-1	CHASSIS (U. S) SUB ASSY		103	3-011-997-01	SPRING (STOPPER. LOWER)	
102	3-024-161-01	SPRING (SUT)		#3	7-685-781-09	SCREW +PTT 2X4 (S)	

7-3. MECHANISM DECK SECTION-2
(MG-251B-137)



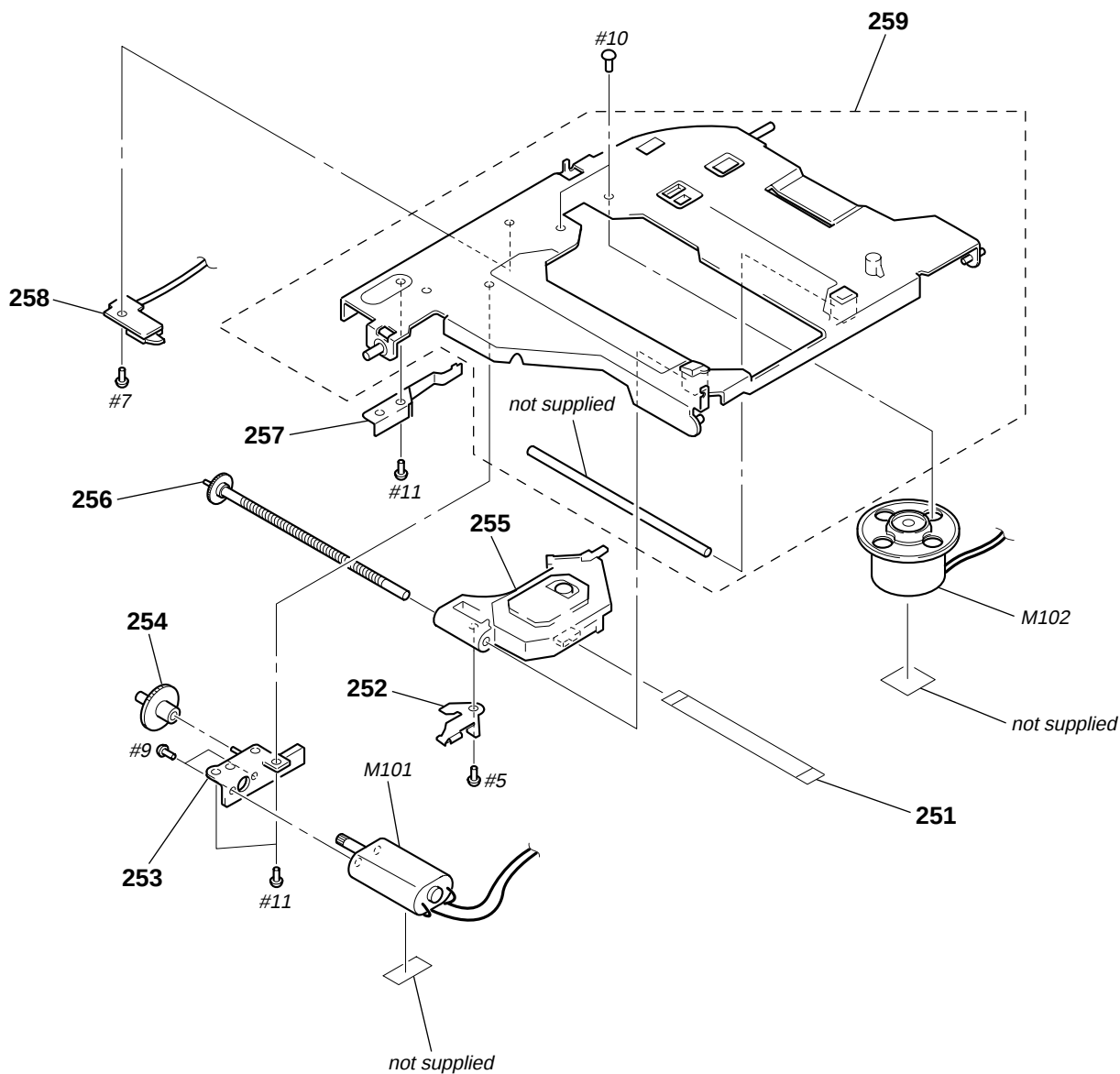
Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
151	3-024-170-01	SPRING (SB), TENSION		* 154	3-014-685-01	SPACER (MO)	
* 152	3-040-790-02	BRACKET (EVM. S)		M104	A-3301-123-A	ELJ MOTOR ASSY (ELEVATOR)	
153	X-3378-092-7	CHASSIS (D. S) SUB ASSY		#3	7-685-781-09	SCREW +PTT 2X4 (S)	

7-4. MECHANISM DECK SECTION-3
(MG-251B-137)



Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
* 201	3-024-150-01	RETAINER (CHM)		* 211	A-3290-194-L	MAIN ASSY, CHASSIS (EVY)	
* 202	X-3378-080-1	BRACKET (CHM. D) ASSY		212	3-010-254-11	SHAFT (ROTARY PREVENTION C)	
204	3-321-813-01	WASHER, COTTER POLYETHYLENE		213	3-010-253-01	GEAR (LOMINI)	
205	3-017-139-01	GEAR (WORM LOAD A)		* 214	A-3326-947-A	RF BOARD, COMPLETE	
206	3-022-839-02	ARM (NSW)		M103	A-3301-123-A	ELJ MOTOR ASSY (CHUCKING)	
207	3-573-936-00	STOPPER, REEL		#3	7-685-781-09	SCREW +PTT 2X4 (S)	
208	X-3373-552-1	GEAR (LOAD 1) ASSY		#4	7-624-104-04	STOP RING 2.0, TYPE-E	
209	3-010-252-11	ROLLER (CRE)		#6	7-628-253-00	SCREW +PS 2X4	
210	3-010-268-01	SPRING (DH), TENSION		#8	7-624-102-04	STOP RING 1.5, TYPE-E	

7-5. MECHANISM DECK SECTION-4 (MG-251B-137)



The components identified by mark $\triangle$ or dotted line with mark $\triangle$ are critical for safety. Replace only with part number specified.

Les composants identifiés par une marque $\triangle$ sont critiques pour la sécurité. Ne les remplacer que par une pièce portant le numéro spécifié.

Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
251	1-676-341-11	OP FLEXIBLE BOARD		259	A-3301-954-B	BASE (OPT. S) (J) ASSY	
252	3-025-743-01	SPRING (FEED), LEAF		M101	A-3315-151-A	SLED MOTOR ASSY (251)	
253	X-3378-101-1	HOLDER (SLED. S) ASSY		M102	A-3301-998-A	SPINDLE MOTOR (S) SUB ASSY	
254	3-931-832-01	GEAR (SL MIDWAY)		#5	7-627-554-07	SCREW, PRECISION +P 2X2.2	
$\triangle$ 255	8-820-103-11	OPTICAL PICK-UP KSS-720A/C-RP		#7	7-627-553-27	SCREW, PRECISION +P 2X2.5	
256	A-3291-669-A	SHAFT (FEED) ASSY		#9	7-627-850-28	SCREW, PRECISION +P 1.4X3	
257	3-010-263-01	DETENT (SHAFT THRUST)		#10	7-627-000-00	SCREW, PRECISION +P 1.7X2.2 TYPE 3	
* 258	1-679-422-12	LSW BOARD		#11	7-627-553-37	PRECISION SCREW +P 2X3 TYPE 3	

SECTION 8
ELECTRICAL PARTS LIST

JACK MAIN

- NOTE:
- Due to standardization, replacements in the parts list may be different from the parts specified in the diagrams or the components used on the set.
 - -XX and -X mean standardized parts, so they may have some difference from the original one.
 - RESISTORS
All resistors are in ohms.
METAL: Metal-film resistor.
METAL OXIDE: Metal oxide-film resistor.
F: nonflammable

- Items marked “*” are not stocked since they are seldom required for routine service. Some delay should be anticipated when ordering these items.
- SEMICONDUCTORS
In each case, u: μ , for example:
uA. . : μ A. . uPA. . : μ PA. .
uPB. . : μ PB. . uPC. . : μ PC. .
uPD. . : μ PD. .
• CAPACITORS
uF: μ F
• COILS
uH: μ H

The components identified by mark Δ or dotted line with mark Δ are critical for safety. Replace only with part number specified.

Les composants identifiés par une marque Δ sont critiques pour la sécurité. Ne les remplacer que par une pièce portant le numéro spécifié.

When indicating parts by reference number, please include the board.

Ref. No.	Part No.	Description	Remark			Ref. No.	Part No.	Description	Remark		
	1-681-577-11	JACK BOARD *****									
		< CAPACITOR >									
C901	1-162-964-11	CERAMIC CHIP	0.001uF	10%	50V	C115	1-128-499-11	ELECT	220uF	20%	16V
C902	1-164-156-11	CERAMIC CHIP	0.1uF		25V	C116	1-128-499-11	ELECT	220uF	20%	16V
C904	1-162-927-11	CERAMIC CHIP	100PF	5%	50V	C119	1-164-156-11	CERAMIC CHIP	0.1uF		25V
C906	1-162-964-11	CERAMIC CHIP	0.001uF	10%	50V	C121	1-162-960-11	CERAMIC CHIP	220PF	10%	50V
		< CONNECTOR >				C122	1-162-960-11	CERAMIC CHIP	220PF	10%	50V
CN901	1-779-077-51	PLUG, CONNECTOR (CONTROL, AUDIO OUT)				C123	1-107-826-11	CERAMIC CHIP	0.1uF	10%	16V
CNJ901	1-778-775-21	CONNECTOR, FPC 13P				C201	1-164-156-11	CERAMIC CHIP	0.1uF		25V
		< DIODE >				C203	1-164-156-11	CERAMIC CHIP	0.1uF		25V
D901	8-719-978-33	DIODE DTZ-TT11-6.8B				C204	1-164-156-11	CERAMIC CHIP	0.1uF		25V
D902	8-719-978-33	DIODE DTZ-TT11-6.8B				C205	1-107-826-11	CERAMIC CHIP	0.1uF	10%	16V
D903	8-719-017-94	DIODE MA8180				C206	1-164-156-11	CERAMIC CHIP	0.1uF		25V
D904	8-719-017-94	DIODE MA8180				C301	1-164-156-11	CERAMIC CHIP	0.1uF		25V
		< FERRITE BEAD >				C302	1-164-156-11	CERAMIC CHIP	0.1uF		25V
FB901	1-500-445-21	FERRITE	0uH			C303	1-164-156-11	CERAMIC CHIP	0.1uF		25V
FB902	1-500-445-21	FERRITE	0uH			C304	1-164-156-11	CERAMIC CHIP	0.1uF		25V
FB903	1-500-445-21	FERRITE	0uH			C306	1-162-968-11	CERAMIC CHIP	0.0047uF	10%	50V
		< IC LINK >				C307	1-128-934-11	CERAMIC CHIP	0.33uF	20%	10V
PS901	1-532-686-21	LINK, IC				C308	1-107-826-11	CERAMIC CHIP	0.1uF	10%	16V
*****						C309	1-162-970-11	CERAMIC CHIP	0.01uF	10%	25V
	A-3283-194-A	MAIN BOARD, COMPLETE *****				C310	1-115-466-00	ELECT	1000uF	20%	16V
	1-676-339-12	MAIN FLEXIBLE BOARD				C311	1-125-972-61	ELECT	100uF	20%	16V
	1-676-340-12	JACK FLEXIBLE BOARD				C312	1-107-826-11	CERAMIC CHIP	0.1uF	10%	16V
		< CAPACITOR >				C313	1-125-972-61	ELECT	100uF	20%	16V
C101	1-164-156-11	CERAMIC CHIP	0.1uF		25V	C314	1-164-156-11	CERAMIC CHIP	0.1uF		25V
C103	1-164-156-11	CERAMIC CHIP	0.1uF		25V	C315	1-115-466-00	ELECT	1000uF	20%	16V
C104	1-162-965-11	CERAMIC CHIP	0.0015uF	10%	50V	C316	1-125-972-61	ELECT	100uF	20%	16V
C105	1-165-176-11	CERAMIC CHIP	0.047uF	10%	16V	C317	1-164-156-11	CERAMIC CHIP	0.1uF		25V
C106	1-162-967-11	CERAMIC CHIP	0.0033uF	10%	50V	C318	1-164-156-11	CERAMIC CHIP	0.1uF		25V
C107	1-162-960-11	CERAMIC CHIP	220PF	10%	50V	C319	1-128-499-11	ELECT	220uF	20%	16V
C108	1-164-156-11	CERAMIC CHIP	0.1uF		25V	C407	1-124-589-11	ELECT	47uF	20%	16V
C109	1-162-970-11	CERAMIC CHIP	0.01uF	10%	25V	C408	1-164-156-11	CERAMIC CHIP	0.1uF		25V
C110	1-125-837-11	CERAMIC CHIP	1uF	10%	6.3V	C409	1-126-157-11	ELECT	10uF	20%	16V
C112	1-164-156-11	CERAMIC CHIP	0.1uF		25V	C410	1-126-157-11	ELECT	10uF	20%	16V
						C411	1-162-927-11	CERAMIC CHIP	100PF	5%	50V
						C412	1-162-927-11	CERAMIC CHIP	100PF	5%	50V
						C413	1-162-927-11	CERAMIC CHIP	100PF	5%	50V
						C414	1-162-927-11	CERAMIC CHIP	100PF	5%	50V
						C418	1-164-156-11	CERAMIC CHIP	0.1uF		25V
						C419	1-124-589-11	ELECT	47uF	20%	16V
						C431	1-162-964-11	CERAMIC CHIP	0.001uF	10%	50V
						C501	1-162-927-11	CERAMIC CHIP	100PF	5%	50V
						C502	1-162-927-11	CERAMIC CHIP	100PF	5%	50V
						C503	1-162-964-11	CERAMIC CHIP	0.001uF	10%	50V

MAIN

LSW

RF

Ref. No.	Part No.	Description	Remark			Ref. No.	Part No.	Description	Remark		
C504	1-162-964-11	CERAMIC CHIP	0.001uF	10%	50V	R304	1-216-847-11	METAL CHIP	150K	5%	1/16W
C505	1-124-589-11	ELECT	47uF	20%	16V	R305	1-216-845-11	METAL CHIP	100K	5%	1/16W
C506	1-124-589-11	ELECT	47uF	20%	16V	R306	1-216-841-11	METAL CHIP	47K	5%	1/16W
< DIODE >						R309	1-216-841-11	METAL CHIP	47K	5%	1/16W
D301	8-719-071-34	DIODE	RB521S-30-TE61			R310	1-216-845-11	METAL CHIP	100K	5%	1/16W
D304	8-719-071-34	DIODE	RB521S-30-TE61			R311	1-216-845-11	METAL CHIP	100K	5%	1/16W
D305	8-719-071-34	DIODE	RB521S-30-TE61			R403	1-218-867-11	RES-CHIP	6.8K	2%	1/16W
D306	8-719-069-56	DIODE	UDZSTE-176.2B			R404	1-218-867-11	RES-CHIP	6.8K	2%	1/16W
D307	8-719-988-61	DIODE	1SS355TE-17			R405	1-218-867-11	RES-CHIP	6.8K	2%	1/16W
D310	8-719-977-03	DIODE	DTZ5.6B			R406	1-218-867-11	RES-CHIP	6.8K	2%	1/16W
D312	8-719-978-33	DIODE	DTZ-TT11-6.8B			R407	1-216-830-11	METAL CHIP	5.6K	5%	1/16W
< IC >						R408	1-216-839-11	METAL CHIP	33K	5%	1/16W
IC101	8-752-402-31	IC	CXD3017Q			R409	1-219-316-11	RES-CHIP	12K	2%	1/16W
IC201	6-800-418-01	IC	MB90473PFV-G-111-BNDE1			R410	1-219-316-11	RES-CHIP	12K	2%	1/16W
IC301	8-759-527-33	IC	LB1930M-TLM			R411	1-219-316-11	RES-CHIP	12K	2%	1/16W
IC302	8-759-829-46	IC	BA8272AFV-E2			R412	1-219-316-11	RES-CHIP	12K	2%	1/16W
IC303	8-759-827-97	IC	XC61CN2502PR			R413	1-219-274-11	RES-CHIP	220	2%	1/16W
IC304	8-759-833-13	IC	NJM2395AF08			R414	1-219-274-11	RES-CHIP	220	2%	1/16W
IC305	8-759-833-12	IC	NJM2395AF05			R415	1-216-845-11	METAL CHIP	100K	5%	1/16W
IC306	8-759-444-93	IC	RH5RL33AA-T1			R416	1-216-845-11	METAL CHIP	100K	5%	1/16W
IC401	8-759-662-11	IC	TLV2362IPWR			R417	1-216-830-11	METAL CHIP	5.6K	5%	1/16W
< TRANSISTOR >						R418	1-216-839-11	METAL CHIP	33K	5%	1/16W
Q202	8-729-901-00	TRANSISTOR	DTC124EK			R420	1-216-864-11	METAL CHIP	0	5%	1/16W
Q302	8-729-230-49	TRANSISTOR	2SC2712-YG			R421	1-218-839-11	RES-CHIP	470	2%	1/16W
Q303	8-729-230-49	TRANSISTOR	2SC2712-YG			R422	1-218-839-11	RES-CHIP	470	2%	1/16W
Q305	8-729-822-84	TRANSISTOR	2SB1202FAST			R501	1-218-871-11	RES-CHIP	10K	2%	1/16W
Q402	8-729-027-23	TRANSISTOR	DTA114EKA-T146			R502	1-218-871-11	RES-CHIP	10K	2%	1/16W
Q410	8-729-015-39	TRANSISTOR	DTC323TK			R503	1-218-871-11	RES-CHIP	10K	2%	1/16W
Q420	8-729-015-39	TRANSISTOR	DTC323TK			R504	1-218-871-11	RES-CHIP	10K	2%	1/16W
< RESISTOR >						R505	1-218-871-11	RES-CHIP	10K	2%	1/16W
R101	1-216-839-11	METAL CHIP	33K	5%	1/16W	R506	1-218-871-11	RES-CHIP	10K	2%	1/16W
R102	1-216-833-11	METAL CHIP	10K	5%	1/16W	< VARIABLE RESISTOR >					
R103	1-216-827-11	METAL CHIP	3.3K	5%	1/16W	RV201	1-223-834-11	RES, ADJ, CARBON 47K			
R104	1-216-827-11	METAL CHIP	3.3K	5%	1/16W	< SWITCH >					
R105	1-216-857-11	METAL CHIP	1M	5%	1/16W	SW201	1-529-565-41	SWITCH, PUSH (1KEY) (MAGAZINE DETECT)			
R106	1-216-853-11	METAL CHIP	470K	5%	1/16W	< VIBRATOR >					
R107	1-216-833-11	METAL CHIP	10K	5%	1/16W	X201	1-781-282-11	VIBRATOR, CERAMIC (4MHz)			
R114	1-216-821-11	METAL CHIP	1K	5%	1/16W	X501	1-760-307-11	VIBRATOR, CERAMIC (16.9344MHz)			
R122	1-216-839-11	METAL CHIP	33K	5%	1/16W	*****					
R123	1-216-845-11	METAL CHIP	100K	5%	1/16W	*	1-679-422-12	LSW BOARD			
R125	1-216-839-11	METAL CHIP	33K	5%	1/16W	*****					
R201	1-216-833-11	METAL CHIP	10K	5%	1/16W	< SWITCH >					
R202	1-216-864-11	METAL CHIP	0	5%	1/16W	SW3	1-529-565-41	SWITCH, PUSH (1KEY) (LIMIT)			
R204	1-216-853-11	METAL CHIP	470K	5%	1/16W	*****					
R207	1-216-821-11	METAL CHIP	1K	5%	1/16W	*	A-3326-947-A	RF BOARD, COMPLETE			
R210	1-216-821-11	METAL CHIP	1K	5%	1/16W	*****					
R211	1-216-845-11	METAL CHIP	100K	5%	1/16W	< CAPACITOR >					
R221	1-216-833-11	METAL CHIP	10K	5%	1/16W	C101	1-107-826-11	CERAMIC CHIP	0.1uF	10%	16V
R222	1-216-833-11	METAL CHIP	10K	5%	1/16W	C102	1-126-206-11	ELECT CHIP	100uF	20%	6.3V
R223	1-216-821-11	METAL CHIP	1K	5%	1/16W	C103	1-164-156-11	CERAMIC CHIP	0.1uF		25V
R301	1-216-841-11	METAL CHIP	47K	5%	1/16W	C104	1-107-826-11	CERAMIC CHIP	0.1uF	10%	16V
R302	1-216-845-11	METAL CHIP	100K	5%	1/16W						
R303	1-216-846-11	METAL CHIP	120K	5%	1/16W						

RF

SWITCH

Ref. No.	Part No.	Description	Remark		
C105	1-126-206-11	ELECT CHIP	100uF	20%	6.3V
C106	1-164-156-11	CERAMIC CHIP	0.1uF		25V
C107	1-164-156-11	CERAMIC CHIP	0.1uF		25V
C108	1-107-826-11	CERAMIC CHIP	0.1uF	10%	16V
C109	1-164-156-11	CERAMIC CHIP	0.1uF		25V
C111	1-107-826-11	CERAMIC CHIP	0.1uF	10%	16V
C121	1-126-206-11	ELECT CHIP	100uF	20%	6.3V
C122	1-164-156-11	CERAMIC CHIP	0.1uF		25V
C201	1-117-681-11	ELECT CHIP	100uF	20%	16V
C202	1-164-156-11	CERAMIC CHIP	0.1uF		25V
C203	1-162-962-11	CERAMIC CHIP	470PF	10%	50V
C204	1-162-962-11	CERAMIC CHIP	470PF	10%	50V
C205	1-162-962-11	CERAMIC CHIP	470PF	10%	50V
C206	1-162-962-11	CERAMIC CHIP	470PF	10%	50V
C207	1-164-227-11	CERAMIC CHIP	0.022uF	10%	25V
C208	1-164-227-11	CERAMIC CHIP	0.022uF	10%	25V
C209	1-164-227-11	CERAMIC CHIP	0.022uF	10%	25V
C217	1-164-156-11	CERAMIC CHIP	0.1uF		25V
< CONNECTOR >					
CN102	1-778-303-21	CONNECTOR, FPC (ZIF) 16P			
CNJ101	1-778-777-21	CONNECTOR, FPC 26P			
< IC >					
IC101	8-752-089-74	IC CXA2581N-T4			
IC201	8-759-832-99	IC LA6576L-TE-L			
< TRANSISTOR >					
Q101	8-729-010-05	TRANSISTOR MSB709-RT1			
Q102	8-729-024-88	TRANSISTOR MUN2212T1			
< RESISTOR >					
R101	1-216-801-11	METAL CHIP	22	5%	1/16W
R102	1-216-837-11	METAL CHIP	22K	5%	1/16W
R103	1-216-837-11	METAL CHIP	22K	5%	1/16W
R104	1-216-845-11	METAL CHIP	100K	5%	1/16W
R105	1-216-801-11	METAL CHIP	22	5%	1/16W
R106	1-216-864-11	METAL CHIP	0	5%	1/16W
R107	1-216-845-11	METAL CHIP	100K	5%	1/16W
R108	1-216-833-11	METAL CHIP	10K	5%	1/16W
R109	1-216-836-11	METAL CHIP	18K	5%	1/16W
R110	1-216-834-11	METAL CHIP	12K	5%	1/16W
R111	1-216-835-11	METAL CHIP	15K	5%	1/16W
R112	1-216-845-11	METAL CHIP	100K	5%	1/16W
R113	1-218-859-11	METAL CHIP	3.3K	0.5%	1/10W
R116	1-216-833-11	METAL CHIP	10K	5%	1/16W
R117	1-216-833-11	METAL CHIP	10K	5%	1/16W
R120	1-218-879-11	METAL CHIP	22K	0.5%	1/10W
R121	1-218-847-11	METAL CHIP	1K	0.5%	1/10W
R122	1-218-847-11	METAL CHIP	1K	0.5%	1/10W
R201	1-216-826-11	METAL CHIP	2.7K	5%	1/16W
R202	1-216-833-11	METAL CHIP	10K	5%	1/16W
R203	1-216-833-11	METAL CHIP	10K	5%	1/16W
R204	1-216-839-11	METAL CHIP	33K	5%	1/16W
R205	1-216-833-11	METAL CHIP	10K	5%	1/16W
R206	1-216-839-11	METAL CHIP	33K	5%	1/16W
R207	1-216-833-11	METAL CHIP	10K	5%	1/16W

Ref. No.	Part No.	Description	Remark		
R208	1-216-839-11	METAL CHIP	33K	5%	1/16W
R209	1-216-833-11	METAL CHIP	10K	5%	1/16W
R210	1-216-839-11	METAL CHIP	33K	5%	1/16W
R211	1-216-833-11	METAL CHIP	10K	5%	1/16W
R212	1-216-839-11	METAL CHIP	33K	5%	1/16W
R213	1-216-833-11	METAL CHIP	10K	5%	1/16W
R214	1-216-839-11	METAL CHIP	33K	5%	1/16W
R215	1-216-841-11	METAL CHIP	47K	5%	1/16W
R216	1-216-842-11	METAL CHIP	56K	5%	1/16W
R218	1-216-841-11	METAL CHIP	47K	5%	1/16W
R219	1-216-843-11	METAL CHIP	68K	5%	1/16W
R220	1-216-834-11	METAL CHIP	12K	5%	1/16W
R222	1-216-821-11	METAL CHIP	1K	5%	1/16W
R223	1-216-819-11	METAL CHIP	680	5%	1/16W
< SWITCH >					
SW1	1-529-566-31	SWITCH, PUSH (1KEY) (CHUKING END DETECT)			
SW2	1-529-566-31	SWITCH, PUSH (1KEY) (SAVE END DETECT)			

	1-681-578-11	SWITCH BOARD			

< SWITCH >					
SW801	1-692-431-21	SWITCH, TACTILE (▲)			

MISCELLANEOUS					

251	1-676-341-11	OP FLEXIBLE BOARD			
△255	8-820-103-11	OPTICAL PICK-UP KSS-720A/C-RP			
M101	A-3315-151-A	SLED MOTOR ASSY (251)			
M102	A-3301-998-A	SPINDLE MOTOR (S) SUB ASSY			
M103	A-3301-123-A	ELJ MOTOR ASSY (CHUCKING)			
M104	A-3301-123-A	ELJ MOTOR ASSY (ELEVATOR)			
RV202	1-227-137-11	RES, VAR, SLIDE 10K (ELEVATOR HEIGHT SENSOR)			

ACCESSORIES					

	3-237-508-11	MANUAL, INSRTUCTION (ENGLISH, FRENCH, SPANISH, TRADITIONAL CHINESE)			
	3-237-508-21	MANUAL, INSRTUCTION (ENGLISH, FRENCH, GERMAN, DUTCH, ITALIAN) (CDX-656)			
	3-237-508-31	MANUAL, INSRTUCTION (SPANISH, SWEDISH, PORTUGUESE, POLISH, RUSSIAN, GREEK (CDX-656)			
	A-3301-944-A	MAGAZINE (250) ASSY			

The components identified by mark △ or dotted line with mark △ are critical for safety. Replace only with part number specified.

Les composants identifiés par une marque △ sont critiques pour la sécurité. Ne les remplacer que par une pièce portant le numéro spécifié.

Ref. No.	Part No.	Description	Remark
PARTS FOR INSTALLATION AND CONNECTIONS			

501	3-040-583-21	BRACKET (T)	
* 502	X-3369-824-1	SCREW ASSY	
503	1-590-874-11	CORD, CONNECTION (RCA PIN CORD 5m)	
504	1-590-519-21	CORD (WITH CONNECTOR) (BUS CABLE 5m)	

